



Accelerometer M-A352AD10 Data Sheet



Notice of the Document

NOTICE : PLEASE READ CAREFULLY BELOW BEFORE THE USE OF THIS DOCUMENT ©Seiko Epson Corporation 2022 The content of this document is subject to change without notice.

- 1. This document may not be copied, reproduced, or used for any other purposes, in whole or in part, without the consent of Seiko Epson Corporation("Epson").
- Before purchasing or using Epson products, please contact with our sales representative for the latest information and be always sure to check the latest information published on Epson's official web sites and sources.
- 3. Information provided in this document such as application circuits, programs, usage, etc., are for reference purpose only. Please use the application circuits, programs, usage, etc. in the design of your equipment or systems at your own responsibility. Epson makes no guarantees against any infringements or damages to any third parties' intellectual property rights or any other rights resulting from the information. This document does not grant you any licenses, intellectual property rights or any other rights with respect to Epson products owned by Epson or any third parties.
- 4. Epson is committed to constantly improving quality and reliability, but semiconductor products in general are subject to malfunction and failure. In using Epson products, you shall be responsible for safe design in your products; your hardware, software and systems are designed enough to prevent any harm or damages to life, health or property even if any malfunction or failure might be caused by Epson products. In designing of your products with using Epson products, please be sure to check and comply with the latest information regarding Epson products (this document, specifications, data sheets, manuals, Epson's web site, etc.). When using the information included in the above materials such as product data, chart, technical contents, programs, algorithms and application circuit examples, you shall evaluate your products both in stand-alone basis and within your overall systems. You shall be solely responsible for deciding whether or not to adopt and use Epson products.
- 5. Epson has prepared this document and programs provided in this document carefully to be accurate and dependable, but Epson does not guarantee that the information and the programs are always accurate and complete. Epson assumes no responsibility for any damages which you incurred by due to misinformation in this document and the programs.
- 6. No dismantling, analysis, reverse engineering, modification, alteration, adaptation, reproduction, etc., of Epson products is allowed.
- 7. Epson products have been designed, developed and manufactured to be used in general electronic applications (office equipment, communications equipment, measuring instruments, home electronics, etc.) and applications individually listed in this document ("General Purpose"). Epson products are NOT intended for any use beyond the General Purpose that requires particular/higher quality or reliability in order to refrain from causing any malfunction or failure leading to harm to life, health or serious property damage or severe impact on society, including, but not limited to listed below. Therefore, you are advised to use Epson products only for the General Purpose. Should you desire to buy and use Epson products for the particular purpose other than the General Purpose, Epson makes no warranty and disclaims with respect to Epson products, whether express or implied, including without limitation any implied warranty of merchantability or fitness for any particular purpose.

[Particular purpose]

Space equipment (artificial satellites, rockets, etc.)

- Transportation vehicles and their control equipment (automobiles, aircraft, trains, ships, etc.)
- Medical equipment (other than applications individually listed in this document) / Relay equipment to be placed on sea floor Power station control equipment / Disaster or crime prevention equipment / Traffic control equipment / Financial equipment
- Other applications requiring similar levels of reliability as the above
- 8. Epson products listed in this document and our associated technologies shall not be used in any equipment or systems that laws and regulations in Japan or any other countries prohibit to manufacture, use or sell. Furthermore, Epson products and our associated technologies shall not be used for developing military weapons of mass destruction, military purpose use, or any other military applications. If exporting Epson products or our associated technologies, you shall comply with the Foreign Exchange and Foreign Trade Control Act in Japan, Export Administration Regulations in the U.S.A (EAR) and other export-related laws and regulations in Japan and any other countries and follow the required procedures as provided by the relevant laws and regulations.
- 9. Epson assumes no responsibility for any damages (whether direct or indirect) caused by or in relation with your non-compliance with the terms and conditions in this document.
- 10. Epson assumes no responsibility for any damages (whether direct or indirect) incurred by any third party that you assign, transfer, loan, etc., Epson products.
- 11. For more details or other concerns about this document, please contact our sales representative.
- 12. Company names and product names listed in this document are trademarks or registered trademarks of their respective companies.

2022.08

© Seiko Epson Corporation 2022, All rights reserved.

Table of Contents

1.	Ge	eneral Description	. 1
2.	Sp	pecifications	. 2
2	.1	Absolute Maximum Ratings	2
2	.2	Recommended Operating Condition	2
2	.3	Performance & Electrical Specifications	3
2	.4	Timing Specifications	5
2	.5	Socket Pin Layout and Functions	7
3		echanical Dimensions	
	.1	Outline Dimensions	
-		pical Performance Characteristics	-
4. -			
5.		asic Operation	
-	.1	Connection To Host	
-	.2	Operation Mode	
-	.3	Functional Block	-
-	.4	Data Output Timing	
	.5	Data Ready Signal	
	.6	Sampling Counter	
-	.7	Self Test	
-	.8	Threshold Detection of Accelerometer	
-	.9	External Trigger Input	
-	.10	Checksum	
-	.11	Automatic Start (For UART Auto Sampling Only)	
-	.12	Bias Offset	
-	.13	Tilt Output / Combination Output	
	.14		
-	.15	Measurement with Reduced Noise Floor Condition	
		Bias Temperature Shock Compensation	
5		FILTER	
		7.1 FIR Kaiser Filter	
		7.3 Notes For FIR Filter Usage	
		7.4 Long-Term Filter (HPF, LPF)	
6.	Di	gital Interface	29
	.1	SPI Interface	
•	6.1		
	6.1	.2 SPI Write Timing (Normal Mode)	.30
	6.1	5 ()	
6		UART Interface	
	6.2 6.2		
	6.2	- 50	
	6.2		
6	.3	Data Packet Format	.35
7.	Us	er Registers	37
	.1	BURST Register (Window 0)	
7	.2	MODE_CTRL Register (Window 0)	
M-4	3524	AD10 Data Sheet SEIKO EPSON CORPORATION	

7.3	DIAG_STAT Register (Window 0)	41				
7.4	FLAG(ND/EA) Register (Window 0)42					
7.5	COUNT Register (Window 0)	43				
7.6	TEMP Register (Window 0)	44				
7.7	ACCL Register (Window 0)	44				
7.8	TILT Register (Window 0)	45				
7.9	SIG_CTRL Register (Window 1)	45				
7.10	MSC_CTRL Register (Window 1)	46				
7.11	SMPL CTRL Register (Window 1)	48				
7.12	FILTER CTRL Register (Window 1)	49				
	,					
	SPI Sequence	60				
	2 Register Read and Write (SPI)	00				
-	4 Selftest (SPI)					
-						
	.9 Filter Setting (SPÍ)	63				
	.10 User Defined FIR Filter Coefficients Setting (SPI)	64				
		65				
	14 Alarm Threshold Setting (SPI)	66				
8.2.	1 Power-on Sequence (UART)	67				
~ ~						
8.2.	2 Register Read and Write (UART)	67				
8.2.	 Register Read and Write (UART) Sampling Data (UART) 	67 67				
	 Register Read and Write (UART) Sampling Data (UART) Selftest (UART) 	67 67 68				
	7.13 7.14 7.15 7.16 7.17 7.18 7.19 7.20 7.21 7.22 7.23 7.24 7.25 7.26 7.26 7.27 7.26 7.27 7.28 7.29 7.20 8.1 8.1 8.1 8.1 8.1 8.1 8.1 8.1 8.1 8.1	7.4 FLAG(ND/EA) Register (Window 0) 7.5 COUNT Register (Window 0) 7.6 TEMP Register (Window 0) 7.7 ACCL Register (Window 0) 7.8 TILT Register (Window 0) 7.9 SIG_CTRL Register (Window 1) 7.10 MSC_CTRL Register (Window 1) 7.11 SMPL_CTRL Register (Window 1) 7.12 FLTER_CTRL Register (Window 1) 7.13 JART_CTRL Register (Window 1) 7.14 GLOB_CMD Register (Window 1) 7.15 BURST_CTRL Register (Window 1) 7.16 FIR_UADDR Register (Window 1) 7.17 FIR_UADDR Register (Window 1) 7.18 ILNGFIL_CTRR Register (Window 1) 7.19 LONGFILT_CTRR Register (Window 1) 7.20 LONGFILT_CTRR Register (Window 1) 7.21 XA_OFFSET Register (Window 1) 7.22 XA_OFFSET Register (Window 1) 7.23 ZA_OFFSET Register (Window 1) 7.24 XA_ALARM Register (Window 1) 7.25 YA_ALARM Register (Window 1) 7.26 ZA_OFFSET Register (Window 1) 7.27 PROD_ID Register (Window 1) 7.28				

8. 8. 8. 8. 8. 8. 8.	2.8 2.9 2.10 2.11 2.12 2.13 2.14	Flash Backup (UART)	70 70 71 72 72 72			
9. H	landli	ing Notes7	74			
9.1	Cau	Itions for Use	74			
9.2	Cau	Itions for Storage	74			
9.3		er Cautions				
9.4		ited Warranty				
10 P	0.4 Enniod Warranty					
	-					
11. E	11. Evaluation Tools					
Revis	sion l	History7	77			



1. General Description

The M-A352 is a three axis digital output accelerometer featuring ultra-low noise, high stability, and low power consumption using fine processing technology of Quartz. Incorporating both high accuracy and durability, the versatile M-A352 is well suited to a wide-range of challenging applications such as SHM, seismic observation, condition monitoring for industrial equipment, and pose detection for industrial machinery (i.e. construction machinery/attachments, agricultural machinery/ implements, robots).

Features

- Ultra-low noise : $0.2\mu G/\sqrt{Hz}$ typ.
- Selectable output format: Acceleration / Tilt Angle
- Selectable interface: SPI / UART
- Programmable low-pass digital filters
- Low jitter external trigger function for synchronous sampling
- Solid metallic case (Aluminum, size : 48mm x 24mm x 16mm, weight: 25g)

Applications

- Structural health monitor
- Seismic measurements
- Vibration control and stabilization
- Motion analysis and control

Functional Block Diagram

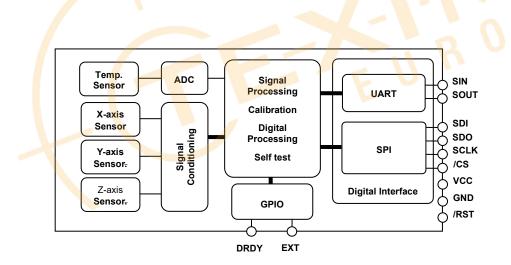


Figure 1.1 Block Diagram

2. Specifications

2.1 Absolute Maximum Ratings

Table 2.1 Absolute Maximum Rating

Parameter	Min	Тур	Max	Unit
VCC to GND	-0.3		3.6	V
Digital Input Voltage to GND	-0.3		VCC+0.3	V
Digital Output Voltage to GND	-0.3		VCC+0.3	V
Storage Temperature Range	-40		85	°C
Acceleration (Half-sine 0.2msec)			1,000	G

^{*1} Precautions concerning ESD.

Electrostatic discharge (ESD) may damage this product.

Please take appropriate measures against electrostatic discharge (ESD) when storing and handling this product.

Damage by electrostatic discharge (ESD) can cause very small performance deterioration, partial malfunction, or complete breakdown.

This is a high precision product and may not conform to specification even with very small performance degradation due to improper usage or handling.

2.2 Recommended Operating Condition

Table 2.2 Recommended Operating Conditions

Parameter	Condition	Min	Тур	Max	Unit
VCC to GND		3.15	3.3	3. <mark>4</mark> 5	V
Digital Input Voltage to GND		GND		VCC	V
Digital Output Voltage to GND		-0.3		VCC +0.3	V
Operating Temperature Range		-30		85	°C
Start up Ti <mark>m</mark> e	Power-on to start output			900	ms.
	W <mark>ar</mark> m-up period for best performance.		F		
	Bias stabilization against thermal shock = enable		5		min.
	Warm-up period for best performance.		45		
	Bias stabilization against thermal shock = disable		15		min

2.3 Performance & Electrical Specifications

Table 2.3 Sensor Specification

Sensitivity Error $25^{\circ}C, \le 1G$ ± 500 \times Nonlinearity $\le 1G$, Best fit straight line, RT ± 0.03 %Cross Axis Sensitivity ± 0.2 $\%$ Misalignment $25^{\circ}C$ ± 0.1 DeBiasInitial Error $25^{\circ}C$ ± 2 mCBias RepeatabilityTA=25^{\circ}C and VCC=3.3V for one year after shipment3mCBias Temperature Error $25^{\circ}C$ ± 2 mCTemperature SensitivityAllan variance, Average 0.2 μ CVelocity Random WalkAverage $1.2E-4$ (mNoiseNoise $1.2E-4$ (mNoise Density $25^{\circ}C$, VCC3.3V 850 HzVRCat 50Hz, $25^{\circ}C$, VCC3.3V ± 50 μ CFrequency Property -6 dB BandwidthUser selectable9 460 TILT ANGLE $5^{\circ}C$ ± 1.0472 rad ($\pm 60)$ (deScale Factor 2^{29} rad/LSB 0.002 μ rrNonlinearity $25^{\circ}C$, $\pm 45deg$ ± 0.03 %Misalignment $25^{\circ}C$ ± 1.745 mrBias $25^{\circ}C$ ± 1.745 mrMonlinearity $25^{\circ}C$ ± 1.745 mrInterver $25^{\circ}C$ ± 1.745 mrBiasBias $1.2E^{\circ}C$ and VCC=3.3V for one ± 3 mr	G/LSB 10 ⁻⁶ (ppm) of FS eg G							
Sensitivity $f = DC \sim 460Hz$ ± 15 GOutput Range $f = DC \sim 460Hz$ 0.06 μ GSensitivity Error $2^{\circ\circ}$ G/LSB 0.06 μ GSensitivity Error $2^{\circ\circ}$ C, ≤ 1 G ± 500 \times Nonlinearity ≤ 1 G, Best fit straight line, RT ± 0.03 $\%$ Cross Axis Sensitivity ± 0.2 $\%$ GMisalignment 25° C ± 0.1 DeBias $=$ $=$ $=$ Initial Error 25° C ± 2 mCBias Repeatabilityyear after shipment 3 mCBias Temperature Error 25° C ± 2 mCTemperature Sensitivity ± 0.1 mCBias InstabilityAllan variance, Average 0.2 μ GVelocity Random WalkAverage 0.2 0.7 μ GNoise $=$ $=$ $=$ $=$ Noise Density 25° C, Avg, f = 0.5Hz ~ 6Hz 0.2 0.7 μ GVRCat 50Hz, 25° C, VCC3.3V ± 50 μ ZVRCat 50Hz, 25° C, VCC3.3V ± 50 μ GFrequency Property $=$ $=$ $=$ -6 dB BandwidthUser selectable 9 460 HTLT ANGLE $=$ $=$ $=$ Sensitivity 25° C, $\pm 456eg$ ± 0.03 $\%$ Monlinearity 25° C, $\pm 45deg$ ± 0.03 $\%$ Misalignment 25° C ± 1.745 m GBias $=$ $=$ $=$ $=$ </td <td>G/LSB 10⁻⁶ (ppm) of FS eg G</td>	G/LSB 10 ⁻⁶ (ppm) of FS eg G							
Output Rangef = DC ~ 460Hz ± 15 GScale Factor 2^{34} G/LSB0.06 μ CSensitivity Error25°C, 51G ± 500 ×Nonlinearity ≤ 1 G, Best fit straight line, RT ± 0.03 %Cross Axis Sensitivity ± 0.2 %Misalignment25°C ± 0.1 DeBiasInitial Error 25° C ± 0.1 DeBiasTA=25°C and VCC=3.3V for one year after shipment3mCBias Temperature Error25°C ± 0.1 mCTemperature Sensitivity ± 0.1 mCBias InstabilityAllan variance, Average0.2 μ CVelocity Random WalkAverage1.2E-4(mNoise $=$ $=$ $=$ Noise Density25°C, VCC3.3V850HzVRCat 50Hz, 25°C, VCC3.3V ± 50 μ CVRCat 50Hz, 25°C, VCC3.3V ± 1.0472 racVRC $=$ $=$ $=$ Noise $=$ $=$ $=$ Noise $=$ $=$ $=$ Norke $=$ $=$ $=$ Noise Density25°C, VCC3.3V $=$ $=$ URC $=$ $=$ $=$ $=$ Norke $=$ $=$ $=$ Norke $=$ $=$ $=$ Norke $=$ $=$ $=$ Norke $=$ $=$ $=$ Sensitivity $=$ $=$ $=$ Dynamic Range $f =$ DC ~ 460Hz $=$ <td>G/LSB 10⁻⁶ (ppm) of FS eg G</br></td>	G/LSB 10 ⁻⁶ (ppm) of FS 							
Scale Factor 2^{24} G/LSB0.06 μ GSensitivity Error25°C, ≤ 1G±500×Nonlinearity≤ 1G, Best fit straight line, RT±0.03%Cross Axis Sensitivity±0.2%Misalignment25°C±0.1Bias1nitial Error25°C±0.1Bias RepeatabilityTA=25°C and VCC=3.3V for one year after shipment3mCBias Temperature Error25°C±2mCTemperature Sensitivity±0.1mCBias InstabilityAllan variance, Average0.2 μ GVelocity Random WalkAverage1.2E-4(mNoise Density25°C, Avg, f = 0.5Hz ~ 6Hz0.20.7 μ GVRCat 50Hz, 25°C, VCC3.3V850HzVRCat 50Hz, 25°C, VCC3.3V±50µGVRCat 50Hz, 25°C, VCC3.3V±60HTILT ANGLESensitivity50.002 μ raScale Factor2 ²⁰ rad/LSB0.002 μ raNonlinearity25°C, ±45deg±0.03%Misalignment25°C±1.745mr (±0.0)Bias5°C±1.745mr (±0.1)BiasEractor2 ²⁰ rad/LSB0.002 μ raSensitivity25°C, ±45deg±0.03%Misalignment25°C±1.745mr (±0.1)BiasBiasTA=25°C and VCC=3.3V for one±3mr	G/LSB 10 ⁻⁶ (ppm) of FS eg G							
Sensitivity Error $25^{\circ}C, \le 1G$ ± 500 \times Nonlinearity $\le 1G$, Best fit straight line, RT ± 0.03 %Cross Axis Sensitivity ± 0.2 $\%$ Misalignment $25^{\circ}C$ ± 0.1 DeBiasInitial Error $25^{\circ}C$ ± 2 mCBias RepeatabilityTA=25^{\circ}C and VCC=3.3V for one year after shipment3mCBias Temperature Error $25^{\circ}C$ ± 2 mCTemperature SensitivityAllan variance, Average 0.2 μ CVelocity Random WalkAverage $1.2E-4$ (mNoiseNoise $1.2E-4$ (mNoise Density $25^{\circ}C$, VCC3.3V 850 HzVRCat 50Hz, $25^{\circ}C$, VCC3.3V ± 50 μ CFrequency Property -6 dB BandwidthUser selectable9 460 HTILT ANGLE $5^{\circ}C$ ± 1.0472 rad ($\pm 60)$ (deScale Factor 2^{*2} rad/LSB 0.002 μ rrNonlinearity $25^{\circ}C$, $\pm 45deg$ ± 0.03 %Misalignment $25^{\circ}C$ ± 1.745 mrBias $5^{\circ}C$ ± 1.745 mrStartivity $5^{\circ}C$ ± 1.0472 radBias $5^{\circ}C$ $5^{\circ}C$ $5^{\circ}C$ Startivity </td <td>10⁻⁶ (ppm) of FS eg G</td>	10 ⁻⁶ (ppm) of FS eg G							
Nonlinearity \leq 1G, Best fit straight line, RT \pm 0.03%Cross Axis Sensitivity \pm 0.2%Misalignment25°C \pm 0.1DeBiasInitial Error25°C \pm 0.1Bias RepeatabilityTA=25°C and VCC=3.3V for one year after shipment3mCBias Temperature Error25°C \pm 2mCTemperature SensitivityAllan variance, Average0.2 μ GVelocity Random WalkAverage1.2E-4(mNoiseNoise Density25°C, Avg, f = 0.5Hz ~ 6Hz0.20.7VRCat 50Hz, 25°C, VCC3.3V \pm 50 μ GVRCat 50Hz, 25°C, VCC3.3V \pm 50 μ GSensitivity 55° \pm 1.0472radMonlinearity25°C, 445deg \pm 0.03%Misalignment25°C \pm 1.745mrBiasBiasTA=25°C and VCC=3.3V for one \pm 3mr	of FS eg G							
Cross Axis Sensitivity ± 0.2 ± 0.2 ± 0.2 ± 0.1 DeBiasInitial Error 25° C ± 0.1 DeBiasInitial Error 25° C ± 2 mCBias RepeatabilityTA=25^{\circ}C and VCC=3.3V for one year after shipment3mCBias Temperature Error 25° C ± 2 mCTemperature Sensitivity ± 0.1 mCBias InstabilityAllan variance, Average 0.2 μ CVelocity Random WalkAverage $1.2E-4$ (mNoise 25° C, Avg, f = 0.5Hz ~ 6Hz 0.2 0.7 μ CCantilever Resonance Frequency ¹¹ 25° C, VCC3.3V 850 HzVRCat 50Hz, 25° C, VCC3.3V ± 50 μ CFrequency Property -6 dB BandwidthUser selectable9 460 TILT ANGLE 5° C, $\pm 45deg$ ± 0.002 μ raScale Factor 2^{28} rad/LSB 0.002 μ raNonlinearity 25° C, $\pm 45deg$ ± 0.03 %Misalignment 25° C ± 1.745 mrBias 5° C and VCC=3.3V for one ± 3	eg G							
Misalignment25°C ± 0.1 DeBiasInitial Error25°C ± 2.1 mCBias RepeatabilityTA=25°C and VCC=3.3V for one year after shipment3mCBias Temperature Error25°C ± 2.1 mCTemperature SensitivityAllan variance, Average0.2 μ CVelocity Random WalkAverage0.20.7 μ CNoise Density25°C, Avg, f = 0.5Hz ~ 6Hz0.20.7 μ CCantilever Resonance Frequency*125°C, VCC3.3V850HzVRCat 50Hz, 25°C, VCC3.3V ± 50 μ CFrequency Property6 dB BandwidthUser selectable9460HTILT ANGLE25°C, ±45deg ± 1.0472 (± 60)(dcScale Factor2 ²⁹ rad/LSB0.002 μ raNonlinearity25°C, ±45deg ± 0.03 %Misalignment25°C ± 1.745 mrBiasEssensitivityBias50°C ± 1.745 mrScale Factor25°C ± 1.745 mrMonlinearity25°C and VCC=3.3V for one ± 3 mr	eg G							
Bias ± 2 ± 2 m(Bias RepeatabilityTA=25°C and VCC=3.3V for one year after shipment3m(Bias RepeatabilityTA=25°C and VCC=3.3V for one year after shipment3m(Bias Temperature Error25°C ± 2 m(Temperature Sensitivity ± 0.1 m(Bias InstabilityAllan variance, Average0.2 μ GVelocity Random WalkAverage $1.2E-4$ (mNoise $1.2E-4$ (mNoise Density25°C, Avg, f = 0.5Hz ~ 6Hz 0.2 0.7 μ GCantilever Resonance Frequency ¹¹ 25°C, VCC3.3V 850 HzVRCat 50Hz, 25°C, VCC3.3V ± 50 μ GVRCat 50Hz, 25°C, VCC3.3V ± 50 μ GSensitivity $= 10C - 460Hz$ ± 1.0472 radCacle Factor 2^{-39} rad/LSB 0.002 μ radNonlinearity 25° C, ± 45 deg ± 1.745 mrMisalignment 25° C ± 1.745 mrBiasBias $\pm 1.0472^{\circ}$ candVCC=3.3V for one ± 3	G							
Initial Error 25° C ± 2 mcBias RepeatabilityTA=25^{\circ}C and VCC=3.3V for one year after shipment3mcBias Temperature Error 25° C ± 2 mcTemperature Sensitivity ± 0.1 mcBias InstabilityAllan variance, Average 0.2 μ CVelocity Random WalkAverage $1.2E-4$ (mNoiseNoise Density 25° C, Avg, f = 0.5Hz ~ 6Hz 0.2 0.7 μ CCantilever Resonance Frequency ¹¹ 25° C, VCC3.3V 850 HzVRCat 50Hz, 25° C, VCC3.3V ± 50 μ CFrequency Property -6 dB BandwidthUser selectable9 460 TILT ANGLE 5° C, ± 45 deg ± 1.0472 rac (± 60)Scale Factor 2^{29} rad/LSB 0.002 μ ra ± 1.745 Nonlinearity 25° C, ± 45 deg ± 1.745 mr (± 0.1)Bias 5° C ± 1.745 mr (± 0.1)BiasBias 5° C ± 1.745 mr (± 0.1)								
Bias RepeatabilityTA=25°C and VCC=3.3V for one year after shipment3mCBias Temperature Error25°C $\pm 2.$ mCTemperature SensitivityAllan variance, Average0.2 μ CVelocity Random WalkAverage1.2E-4(mNoiseNoise Density25°C, Avg, f = 0.5Hz ~ 6Hz0.20.7Cantilever Resonance Frequency'125°C, VCC3.3V850HzVRCat 50Hz, 25°C, VCC3.3V25°C, VCC3.3V25°CVRCat 50Hz, 25°C, VCC3.3V460HTILT ANGLE5(dd)HSensitivity25°C, ±45deg0.002 μ raNonlinearity25°C, ±45deg±1.0472radMisalignment25°C±1.745mrBias RepeatabilityTA=25°C and VCC=3.3V for one±3mr								
Bias Repeatabilityyear after shipment3mGBias Temperature Error $25^{\circ}C$ ± 2 mGTemperature Sensitivity ± 0.1 mGBias InstabilityAllan variance, Average 0.2 μ GVelocity Random WalkAverage $1.2E-4$ (mNoise $1.2E-4$ (mNoise Density $25^{\circ}C$, Avg, f = $0.5Hz \sim 6Hz$ 0.2 0.7 μ GCantilever $25^{\circ}C$, VCC3.3V 850 HzVRCat $50Hz$, $25^{\circ}C$, VCC3.3V ± 50 μ GFrequency Property -6 dB BandwidthUser selectable 9 460 HTILT ANGLE $5^{\circ}C$, $\pm 460Hz$ ± 1.0472 rad ($\pm 60)$ (dediced)Scale Factor $2^{29}rad/LSB$ 0.002 μ rad ($\pm 0.13)$ ϕ GMisalignment $25^{\circ}C$ ± 1.745 mr ($\pm 0.1)$ (dediced)BiasTA= $25^{\circ}C$ and VCC= $3.3V$ for one ± 3 mr	G							
Bias Temperature Error $25^{\circ}C$ ± 2 mCTemperature Sensitivity ± 0.1 mCBias InstabilityAllan variance, Average 0.2 μ CVelocity Random WalkAverage $1.2E-4$ (mNoise $1.2E-4$ (mNoise Density $25^{\circ}C$, Avg, f = $0.5Hz \sim 6Hz$ 0.2 0.7 Cantilever $25^{\circ}C$, VCC3.3V 850 HzVRCat 50Hz, $25^{\circ}C$, VCC3.3V ± 50 μ CFrequency Property -6 dB BandwidthUser selectable 9 460 TILT ANGLE $5^{\circ}C$, $\pm 460Hz$ ± 1.0472 racSensitivity $25^{\circ}C$, $\pm 45deg$ ± 0.03 $\%$ Misalignment $25^{\circ}C$, $\pm 45deg$ ± 0.03 $\%$ Bias $5^{\circ}C$ and VCC=3.3V for one ± 3 mr								
Temperature Sensitivity ± 0.1 modelBias InstabilityAllan variance, Average 0.2 μ GVelocity Random WalkAverage $1.2E-4$ (mNoiseNoise Density 25° C, Avg, f = 0.5 Hz ~ 6Hz 0.2 0.7 μ GCantilever Resonance Frequency*1 25° C, VCC3.3V 850 HzVRCat 50Hz, 25° C, VCC3.3V ± 50 μ GFrequency Property -6 dB BandwidthUser selectable 9 460 HTILT ANGLE 5° C, ± 1.0472 rac ($\pm 60)$ rac ($\pm 60)$ $f = DC \sim 460$ Hz ± 1.0472 rac ($\pm 60)$ Scale Factor 2^{-29} rad/LSB 0.002 μ rac (± 1.745 mr ($\pm 0.1)$ $dental mathematical mathem$	G							
Bias InstabilityAllan variance, Average 0.2 μ GVelocity Random WalkAverage $1.2E-4$ (mNoiseNoise Density 25° C, Avg, f = 0.5Hz ~ 6Hz 0.2 0.7 μ GCantilever Resonance Frequency'1 25° C, VCC3.3V 850 HzVRCat 50Hz, 25° C, VCC3.3V ± 50 μ GFrequency Property -6 dB BandwidthUser selectable 9 460 TILT ANGLE $5000000000000000000000000000000000000$	G/°C							
Velocity Random WalkAverage1.2E-4(mNoiseNoise Density 25° C, Avg, f = 0.5Hz ~ 6Hz0.20.7 μ GCantilever Resonance Frequency*1 25° C, VCC3.3V850HzVRCat 50Hz, 25° C, VCC3.3V ± 50 μ GFrequency Property-6 dB BandwidthUser selectable9460TILT ANGLESensitivityDynamic Range $f = DC \sim 460$ Hz (± 60) (deScale Factor 2^{-29} rad/LSB 0.002 μ raNonlinearity 25° C, ± 45 deg ± 0.03 %Misalignment 25° C ± 1.745 mrBiasTA= 25° C and VCC= $3.3V$ for one ± 3 mr								
Noise25°C, Avg, f = 0.5Hz ~ 6Hz0.20.7 μ GCantilever Resonance Frequency*125°C, VCC3.3V850HzVRCat 50Hz, 25°C, VCC3.3V ± 50 μ GFrequency Property-6 dB BandwidthUser selectable9460TILT ANGLE9460HSensitivity ± 1.0472 racCacle Factor 2^{-29} rad/LSB0.002 μ raNonlinearity25°C, ± 45 deg ± 0.03 %Misalignment25°C ± 1.745 mrBias $\pm 25^\circ$ C and VCC=3.3V for one ± 3 mr	n/sec)/√hr							
Noise Density 25° C, Avg, f = 0.5Hz ~ 6Hz0.20.7µGCantilever Resonance Frequency*1 25° C, VCC3.3V 850 HzVRCat 50Hz, 25° C, VCC3.3V ± 50 µGFrequency Property-6 dB BandwidthUser selectable9460TILT ANGLE9460HSensitivity ± 1.0472 rac (± 60)Scale Factor 2^{-9} rad/LSB 0.002 µra hrac (± 0.03) %Misalignment 25° C, ± 45 deg ± 1.745 BiasTA= 25° C and VCC= $3.3V$ for one ± 3	i/secj/√ m							
Resonance Frequency*1 25° C, VCC3.3V 850 HzVRCat 50Hz, 25° C, VCC3.3V ± 50 μ GFrequency Property-6 dB BandwidthUser selectable9460HTILT ANGLE9460HSensitivity ± 1.0472 radDynamic Range $f = DC \sim 460$ Hz (± 60) (deScale Factor 2^{-29} rad/LSB 0.002 μ radNonlinearity 25° C, ± 45 deg ± 1.745 mrBias ± 1.745 mr(\pm 0.1)(deBias $\pm 125^{\circ}$ C and VCC= $3.3V$ for one ± 3 mr	G/√Hz, rms							
VRCat 50Hz, 25°C, VCC3.3V ± 50 μ GFrequency Property-6 dB BandwidthUser selectable9460HTILT ANGLESensitivityDynamic Range $f = DC \sim 460$ Hz ± 1.0472 rad (± 60)(deScale Factor 2^{-29} rad/LSB 0.002 μ rad (± 0.03)%Nonlinearity 25° C, ± 45 deg ± 1.745 mr (± 0.1)(deBiasTA=25°C and VCC=3.3V for one ± 3 mr	z							
Frequency Property-6 dB BandwidthUser selectable9460HTILT ANGLESensitivityDynamic Range $f = DC \sim 460Hz$ ± 1.0472 rac (± 60)(de (de (de (de))Scale Factor 2^{-29} rad/LSB0.002µra ± 0.03 %Nonlinearity 25° C, $\pm 45deg$ ± 1.745 mr (± 0.1)(de (de))BiasTA=25^{\circ}C and VCC=3.3V for one ± 3 mr	G/G ²							
-6 dB BandwidthUser selectable9460HTILT ANGLESensitivityDynamic Range $f = DC \sim 460$ Hz ± 1.0472 rac (± 60)(de (de (de (de 2))Scale Factor 2^{29} rad/LSB 0.002 μ ra ± 0.03 Nonlinearity 25° C, ± 45 deg ± 1.745 mr (± 0.1)Misalignment 25° C ± 1.745 mr (± 0.1)BiasTA=25^{\circ}C and VCC=3.3V for one ± 3 mr	bio							
TILT ANGLE Sensitivity Dynamic Range $f = DC \sim 460Hz$ Scale Factor 2^{-29} rad/LSB Nonlinearity $25^{\circ}C$, $\pm 45deg$ Misalignment $25^{\circ}C$ Bias TA= $25^{\circ}C$ and VCC= $3.3V$ for one Bias Repeatability TA= $25^{\circ}C$ and VCC= $3.3V$ for one	17							
SensitivityDynamic Range $f = DC \sim 460$ Hz ± 1.0472 rac (± 60)Scale Factor 2^{-29} rad/LSB 0.002 μ ra ± 0.03 Nonlinearity 25° C, ± 45 deg ± 0.03 %Misalignment 25° C ± 1.745 mr (± 0.1)BiasTA=25^{\circ}C and VCC=3.3V for one ± 3 mr	12							
Dynamic Range $f = DC \sim 460Hz$ ± 1.0472 (± 60)rad (de Scale Factor 2^{-29} rad/LSB 0.002 μ radNonlinearity 25° C, ± 45 deg ± 0.03 %Misalignment 25° C ± 1.745 (± 0.1)mr (± 0.1)BiasTA=25^{\circ}C and VCC=3.3V for one ± 3								
Dynamic Range $f = DC \sim 460Hz$ (± 60) (de) Scale Factor $2^{-29}rad/LSB$ 0.002 μra Nonlinearity $25^{\circ}C, \pm 45deg$ ± 0.03 %Misalignment $25^{\circ}C$ ± 1.745 mrBias $TA=25^{\circ}C$ and VCC= $3.3V$ for one ± 3 mr	d							
Nonlinearity 25°C, ±45deg ±0.03 % Misalignment 25°C ±1.745 mr (±0.1) mr (de Bias TA=25°C and VCC=3.3V for one ±3 mr	eg)							
Misalignment 25°C ±1.745 mr (±0.1) mr (de Bias TA=25°C and VCC=3.3V for one ±3 mr	ad/LSB							
Misalignment 25°C (±0.1) (de Bias TA=25°C and VCC=3.3V for one ±3 mr	of FS							
Bias TA=25°C and VCC=3.3V for one ±3 mr	rad							
Bias Repeatability TA=25°C and VCC=3.3V for one ±3 mr	eg)							
Bias Repeatability								
	rad							
year after shipment (±0.17) (de	eg)							
Bias Temperature Error 25°C ±2 mr								
(±0.11) (de	rad							
Noise	rad eg)							
Noise Density 25°C, Avg, f = 0.5Hz ~ 6Hz 0.2 0.7 μra								
TEMPERATURE SENSOR								
Output Range -30 85 °C	eg)							
Scale Factor *2 Output=2634(0x0A4A) at 25°C -0.0037918 °C	eg) ad/√Hz, rms							
RELIABILITY	eg) ad/√Hz, rms							
MTBF*3 JIS-C5003 TA=25°C 87,600 ho	eg) ad/√Hz, rms							

Condition: T_A=-30°C to +85°C, VCC=3.15V~3.45V, ≤±1G, Normal Operation Mode, unless otherwise noted.

^{*1} Please make sure that a vibration on this product around the resonance frequency does not exceed 100 mG. Please take an appropriate action (e.g. installing a damper mechanism) if it exceeds 100 mG.

^{*2} This is a reference value used for the internal temperature correction, and is not guaranteed to accurately output the interior temperature.

 *3 The MTBF is an estimated value derived from the result of high temperature operation with a system requirement of TA=25 $^{\circ}$ C and a 60% reliability level.

Note) The values in the specifications are based on the data calibrated at the factory. The values may change according to the way the product is used.

Note) The Max/Min value is the maximum/minimum value of the design or factory shipment examination, unless otherwise specified. Note) The calibrated standard 1G gravitational acceleration value is 9.80665 m/s^2

Table 2.4 Interface Spe	cification T _A =25°C	, VCC=3.3\	/, unless ot	herwise not	ed
Parameter	Test Conditions	Min	Тур	Max	Unit
LOGIC INPUTS ^{*1}					
Positive Trigger Voltage	Schmitt	1.37		2.29	V
Negative Trigger Voltage	Schmitt	0.69		1.24	V
Hysteresis Voltage	Schmitt	0.53			V
Input Current, li	VI=Vcc or GND		0.5		μA
Input Capacitance, Ci			2.5		pF
RST Low Pulse Width		100			ms
Pull-up resistor			220		kΩ
Ext.Trigger Input Width, t _{ETW}		1			μs
Ext.Trigger Input Cycle, t _{ETC}		1		20	ms
Ext.Trigger Jitter, t _{ETJ}	Ext.Trigger input to resampling's completion	0		5	μs
Ext.Trigger Delay Time*3, t _{ETD}	Ext.Trigger input to DRDY asserted Long-period filter is disable			740	μs
Internal Timer Delay Time ^{*3} , t _{ITD}	Internal Timer input to DRDY asserted Long Period Filter = disable			430	μs
DIGITAL OUTPUTS ^{*1}					
Output High Voltage, VOH	ISOURCE=20µA	VCC-0.1			V
Output Low Voltage, VOL	ISINK=20µA			0.1	V
FUNCTIONAL TIMES ^{*2}	Time until data is available				
Power-On Start-Up Time				900	ms 🥢
Reset Recovery Time				970	ms
Flash Backup <mark>Ti</mark> me				310	ms
Flash Reset Time			0	1900	ms
Self Test Time	ACC Test, TEMP Test, VDD Test		K	200	ms
	Sensitivity Test / axis		10	40	s
	Flash Test			5	ms
Filter Setting Time	Built-In FIR Filter			4	ms
	User FIR Filter			100	ms
User Filter Write Cycle, tuwc				7	ms
User Filter Read Cycle, turc				500	us
Sleep Wake-up Time, t _{WakeUp}				16	ms
OUTPUT DATA RATE		50		1,000	Sps
Clock Accuracy				±0.001	%
POWER SUPPLY	Operating voltage range, VCC	3.15	3.3	3.45	V
Power Supply Current	Standard noise floor condition, 200Sps, Average		13.2	18.0	mA
	Reduced noise floor condition,		16.2	20.0	mA
	200Sps, Average		10	2.0	mA
	Sleep mode		1.3	2.0	mA

Note) These parameters are not included in the factory test items but these characteristics are confirmed.

*1) Digital I/O signal pins operate at 3.3V inside the unit. All digital I/O signal pins (except RST) can tolerate 5V input.

*2) These specifications do not include the effect of temperature fluctuation and response time of the internal filter.

*3) It is not included the group delay of the built-in filter.

2.4 Timing Specifications

Table 2.5 Ti	T _A =25°C, VC	C=3.3V, un	less otherwise	e noted	
Parameter	Description	Min	Тур	Max	Unit
NORMAL MODE		•		·	
fSCLK		0.01		2.0	MHz
tSTALL	Stall period between data	20			μs
tWRITERATE	Write rate	40			μs
tREADRATE	Read rate	40			μs
BURST MODE					
fSCLK		0.01		2.0	MHz
tSTALL1	Stall period between data	45			μs
tSTALL2	Stall period between data	0			μs
tREADRATE2	Read rate	8			μs
COMMON					
tCS	Chip select to clock edge	10			ns
tDAV	SO valid after SCLK edge			80	ns
tDSU	SI setup time before SCLK rising edge	10			ns
tDHD	SI hold time after SCLK rising edge	10			ns
tSCLKR, tSCLKF	SCLK rise/fall times			20	ns
tDF, tDR	SO rise/fall times			20	ns
tSFS	high after SCLK edge CS	80			ns

Note) These parameters are not included in the factory test items but these characteristics are confirmed.

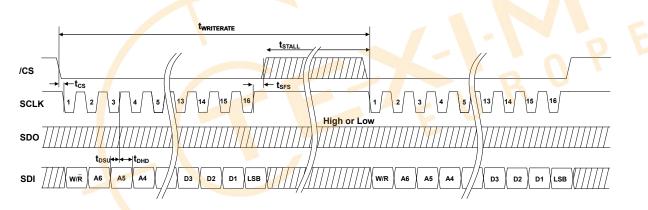
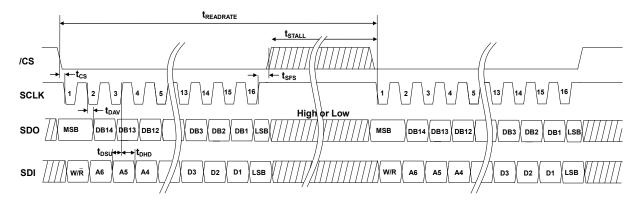
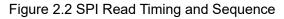


Figure 2.1 SPI Write Timing and Sequence





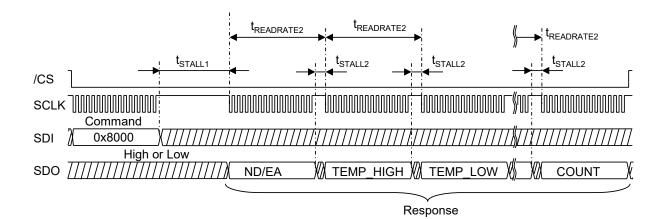


Figure 2.3 SPI Read Timing and Sequence (BURST MODE)



2. Specifications

2.5 Socket Pin Layout and Functions

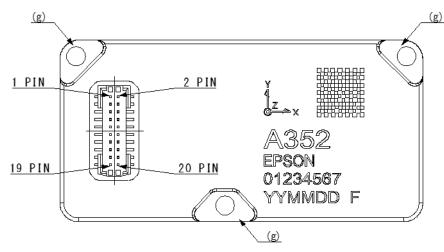


Figure 2.4 Socket Pin Assignment

Table 2.6 Pin Function Descriptions

Pin No.	Mnemonic	Type ^{*1}	Description	
1	SCLK		SPI Serial Clock *2	
2	SDO	0	SPI Data Output *2	
5	SDI		SPI Data Input *2	nt
6	/CS	-	SPI Chip Select *2	
7	SOUT	0	UART Data Output *2	-
9	SIN		UART Data Input *2	
13	DRDY	0	Data Ready *3	
14	EXT		External Trigger Input *4	
14			(Sleep Wakeup Input)	
16	/RST		Reset *5	
10,11,12	VCC	S	Power Supply 3.3V	
3,4,8,15	GND	S	Ground ^{*6}	
17,18,19,20	NC	N/A	Do Not Connect	

*1) Pin Type I :Input, O :Output, I/O :Input/Output, S :Supply, N/A :Not Applicable
*2) Please connect either SPI or UART. Connecting both SPI and UART at the same time may cause malfunction. 2) Please connect entrel SPT of OART. Connecting both SPT and OART at the same time may cause Please connect unused input pins to VCC via a resistor.
*3) Please refer to DRDY_ON of register: MSC_CTRL [0x02 (W1)], bit [2] for pin function selection.
*4) Please refer to EXT_SEL of register: MSC_CTRL [0x02 (W1)], bit [6] for pin function selection.

*5) When RST pin is not used, fix it to High (VCC) level via a resistor.

*6) Please connect (g) Frame Ground to any GND pin (No.3, 4, 8, 15).

Note) All input pins are weak pull-up inside this product.

3. Mechanical Dimensions

3.1 Outline Dimensions

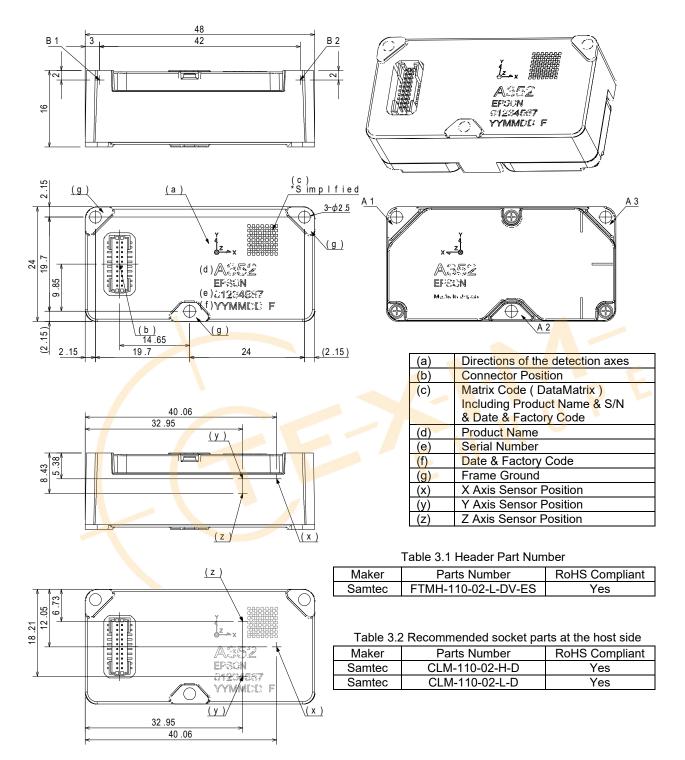
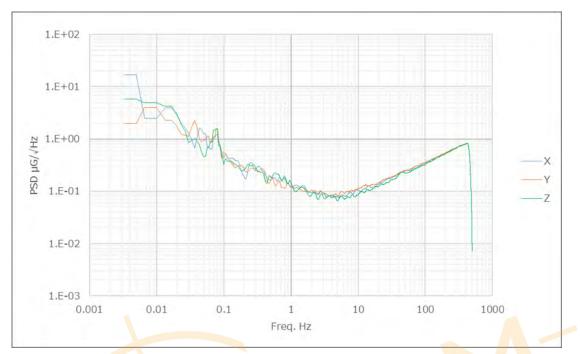


Figure 3.1 Outline Dimensions (millimeters)

*1) This product is calibrated based on the surfaces A1, A2, A3, and B1, B2.

*2) In order to demonstrate the performance of the product properly, please fix surfaces A1, A2, A3 to rugged parts with M2 screw.

*3) When high connection reliability is required, please tighten this product together with the board on which the connector is mounted.



4. Typical Performance Characteristics

Figure 4.1 Noise Density Characteristic of Accelerometer (Standard Noise Floor Condition)

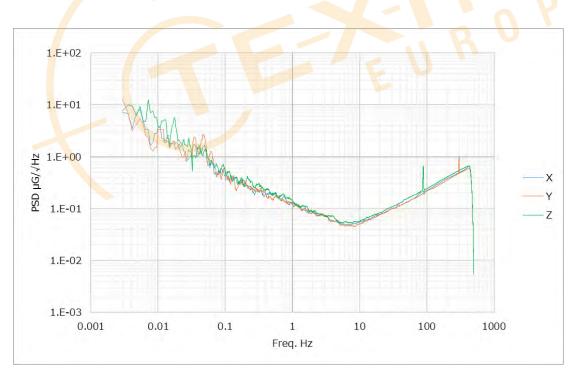


Figure 4.2 Noise Density Characteristic of Accelerometer (Reduced Noise Floor Condition)

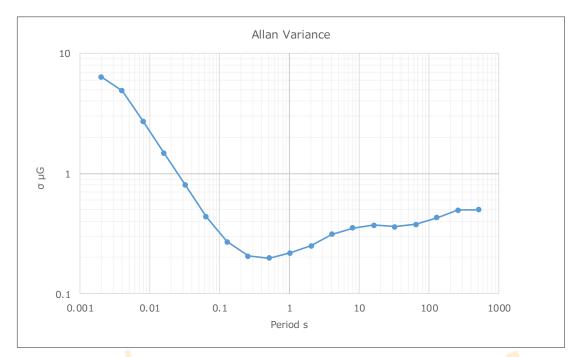


Figure 4.3 Allan Variance Characteristic of Accelerometer(Standard Noise Floor Condition)

The above graph is a typical example of the product characteristics, and is not guaranteed by the specification.

5. Basic Operation

5.1 Connection To Host

The device supports two types of serial interface:UART and SPI. Only one interface type should be selected and used at any given time (not both). The example wiring connection is provided below as a reference.

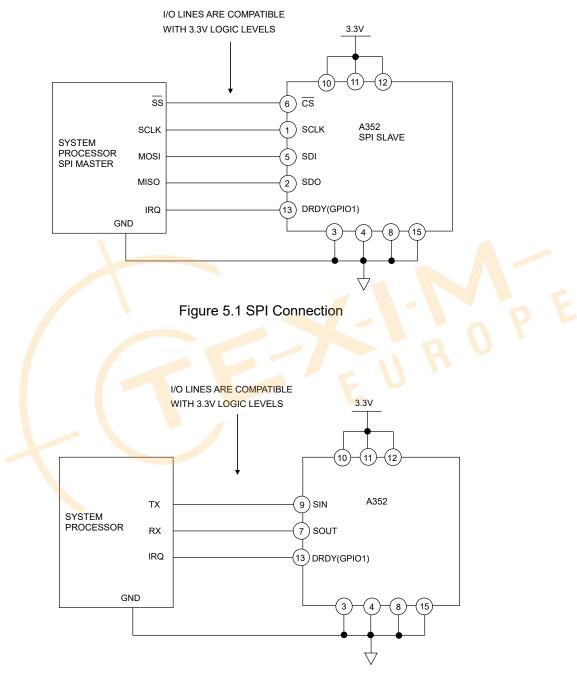


Figure 5.2 UART Connection

The device performance may be affected by signal overshoot or undershoot of the host interface. Care must be taken minimize signal integrity issues when designing the electrical interface so that the noise level is reduced as much as possible to within the tolerance of the communication timing specification.

Measurement condition

Standard noise floor

Reduced noise floor

5.2 **Operation Mode**

The following three operational modes are available in the device.

- (1) Configuration mode
- (2) Sampling mode
 - Sampling condition
 - Manual sampling
 - Auto sampling (UART Only)

(3) Sleep mode

In the Sampling mode, the device can operate with a standard noise floor condition or a reduced noise floor condition. When Auto sampling is active, all sensor outputs are sent automatically at the programmed output data rate without the request from the Host (only available with a UART connection). These conditions can be switched between Manual sampling and Auto sampling by UART AUTO, and between a Standard noise floor and a Reduced noise floor by **MESMOD SEL** (see Figure 5.3).

Immediately after a hardware reset or power-on, internal initialization starts. During the internal initialization, all the register values and states of external pins are undefined. After the internal initialization is completed, the device goes into Configuration mode automatically, except for the UART version when AUTO_START and UART_AUTO sampling are both enabled (the device then goes into Sampling mode automatically). To change the operation mode, write to **MODE CMD** (MODE CTRL[0x02(W0)] bit[9:8]) ^(*1) and make various changes to the sensor setting in Configuration mode (²⁾. After configuration is completed, go to Sampling mode to read out the temperature and acceleration data. When shifting to the sleep mode, the internal circuit operation stops and the current consumption during standby can be reduced. The return time from sleep mode can be shorter than the initialization time from startup. The device can wake up from sleep mode by detecting an edge trigger on the EXT pin.

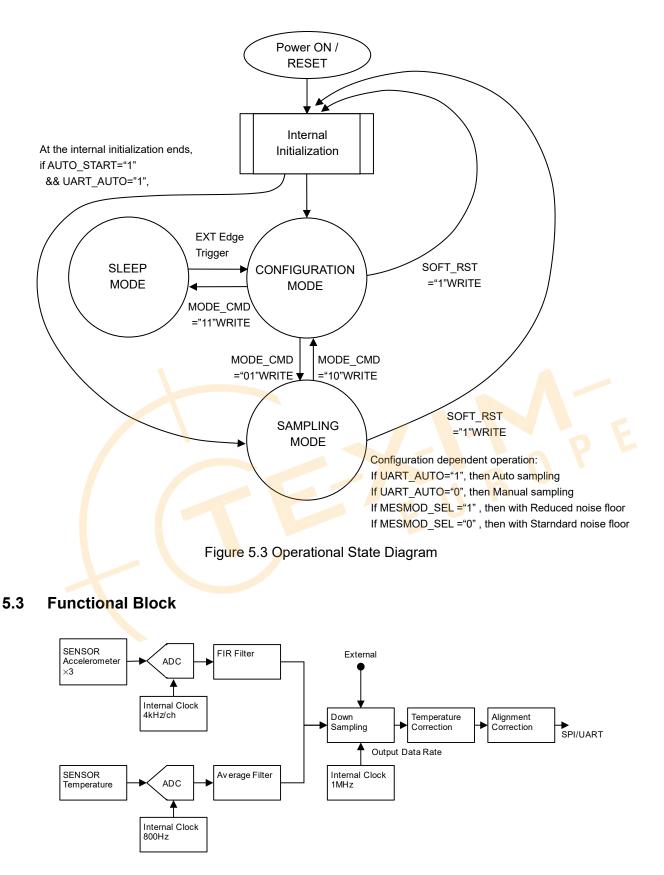
By executing software reset (Register: GLOB CMD [0x0A (W1)], write 1 to SOFT RST in bit [7]), internal initialization operation is executed regardless of the current operation mode and the system enters Configuration mode.

When the UART interface is used, writing to UART_AUTO (UART_CTRL[0x08(W1)] bit[0]) can switch between the Manual sampling and the Auto sampling^(*3). When SPI interface is used, Manual sampling must be selected. Otherwise, the device does not work properly.

*1) The following explains register notation used in this document.

For example, MODE CTRL[0x02(W0)] bit[9:8] refers to:

- MODE CTRL: Register Name
- [0x02(W0)] : First number is the Register Address, (W0) refers to Window Number "0" •
- : Bits from 9 to 8 bit[9:8]
- *2) Make sure that the device is in Configuration mode when you write to the registers to configure operational settings. In Sampling mode, writing to registers is ignored except the following cases.
 - Writing to **MODE CMD** (MODE CTRL[0x02(W0)] bit[9:8])
 - Writing to **SOFT_RST** (GLOB_CMD[0x0A(W1)] bit[7])
 - Writing to WINDOW_ID (WIN CTRL[0x7E(W0/W1)] bit[7:0])
- *3) While the device is with UART Auto sampling and sensor sampling is active, register read access is not supported. Otherwise, the sampling data transmitted with the UART Auto sampling will be corrupted by the response data from the register read.





5. Basic Operation

5.4 Data Output Timing

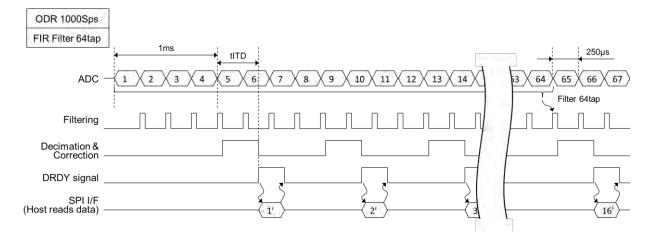
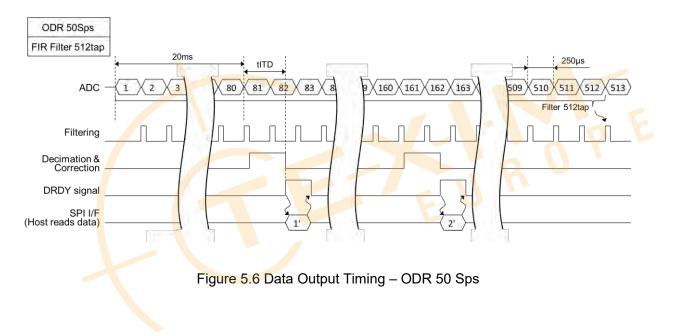


Figure 5.5 Data Output Timing – ODR 1,000 Sps



5.5 Data Ready Signal

The Data Ready Signal is asserted when one sampling cycle completes and registers are updated with new sensor values. When the sensor values are read out, the Data Ready signal becomes negated. With UART AUTO sampling enabled, the Data Ready signal becomes negated just before data is output.

The Data Ready Signal is output to the DRDY pin when the **DRDY_ON** (MSC_CTRL[0x02(W1)] bit[2]) is set to "1". The polarity of the signal can be changed by the **DRDY_POL** of MSC_CTRL[0x02(W1)] bit[1] register.

The Data Ready Signal is the logical sum of all the ND flags corresponding to each sensor value. If all the ND flags are disabled in the **ND_EN** (SIG_CTRL[0x00(W1)] bit[15,11:9]), the Data Ready will not be asserted. On the other hand, if all the sensor values enabled in the **ND_EN** (SIG_CTRL[0x00(W1)] bit[15,11:9]) are not read out, the Data Ready signal is kept asserted and never becomes negated.

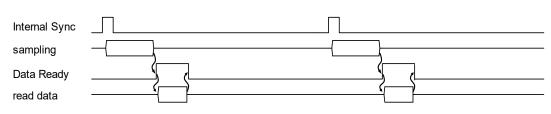


Figure 5.7 Data Ready Signal Timing

5.6 Sampling Counter

By reading COUNT[0x0A(W0)] register, the counter value, which is incremented based on the sampling completion timing of the internal A/D converter, can be read. The count interval is 250usec/count and is based on the precision of the internal reference oscillator (crystal).

Additionally, during UART/SPI burst mode or with UART Auto sampling, the counter value can be included in the response format by setting the **COUNT_OUT** (BURST_CTRL[0x0C(W1)] bit[1]). For information about the response format, see 6.3 DATA PACKET FORMAT.

5.7 Self Test

This product has the following self test functions. For information about the execution time of the self test, see "Self Test Time" in Table 2.4 Interface Specifications.

Acceleration Value

This self test function can be used to check whether the outputs of the accelerometer are within the pre-determined range and operating properly.

The test result is OK if the absolute value of the output as a three dimensional vector is within the gravitational acceleration(0.8G to 1.2G).

When performing the self test, make sure the device does not move during the test and the test is conducted in a place without vibration.

To use this function, execute **ACC_TEST** of register: MSC_CTRL[0x02(W1)] bit[10], check the **ACC_ERR_ALL** of register DIAG_STAT[0x04(W0)] bit[1] for diagnostic result.

Acceleration Sensitivity

This self test function can be used to determine whether the acceleration sensitivity error is within \pm 2.5 %. It takes up to 40 sec (typ.10 sec) per axis for the diagnostic.

To use this function, execute **SENS_TEST** of register: MSC_CTRL[0x02(W1)],bit[14:12], check the **SENS_ERR** of register DIAG_STAT[0x04(W0)],bit[11:10] for diagnostic result.

Note) It may lead to a diagnostic result of "unable to be determined" or may result in an inaccurate diagnostic when there are sudden changes in vibration level during the execution or the vibration level is lower than the noise floor of this product (refer to Section 4 Typical Performance Characteristics).

Temperature Value

Determine whether the temperature sensor is operating properly.

To use this function, execute **TEMP_TEST** of register: MSC_CTRL [0x02 (W1)], bit [9], check the **TEMP_ERR** of register: DIAG_STAT [0x04 (W0)], bit [9] for diagnostic result.

• Power Supply Voltage Level

Determine whether the power supply voltage is within 3.0V to 3.6V.

To use this function, execute **VDD_TEST** of register: MSC_CTRL[0x02(W1)],bit[8], check the **VDD_ERR** of register: DIAG_STAT[0x04(W0)],bit[8] for diagnostic result.

• Nonvolatile memory

Determine whether the Nonvolatile memory is operating properly by consistency test of data in nonvolatile memory.

To use this function, execute **FLASH_TEST** of register: MSC_CTRL[0x02(W1)],bit11], check the **FLASH_ERR** of register: DIAG_STAT[0x04(W0)],bit[2] for diagnostic result.

5.8 Threshold Detection of Accelerometer

When the acceleration value exceeds the preset threshold, an alarm is indicated. The threshold can be set for each 1G step within the range of 0 to 15 G upper limit and -15 G to 0 G lower limit. At the time of shipment, the upper limit + 15 G and the lower limit -15 G are set

The alarm threshold is set in the registers: XA_ALARM [0x47 - 0x46 (W1)], YA_ALARM [0x49 - 0x48 (W1)], ZA_ALARM [0x48 – 0x4A (W1)] and the alarm indication is registered in FLAG [0x06 (W0)], displayed in *ALARM_ERR of bit [4: 2]. Reading *ALARM_ERR will reset the alarm display.

5.9 External Trigger Input

External Trigger Input function provides control of the sample data output timing by using an externally supplied input pulse signal to EXT pin. By enabling the **EXT_SEL** (MSC_CTRL[0x02(W1)] bit[6]), EXT pin can be used as External Trigger Input pin. The polarity of External Trigger Input (Positive Pulse / Negative Pulse) can be selected by **EXT_POL** (MSC_CTRL[0x02(W1)] bit[5]).

When this function is active, the operation is as follows:

For UART Auto Sampling:

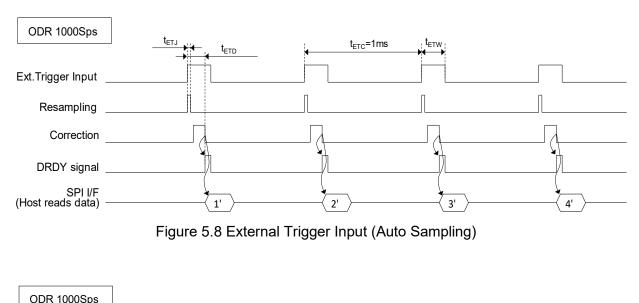
When External Trigger Input pin is asserted, the latest sampling data is set to each register and sent to Host automatically.

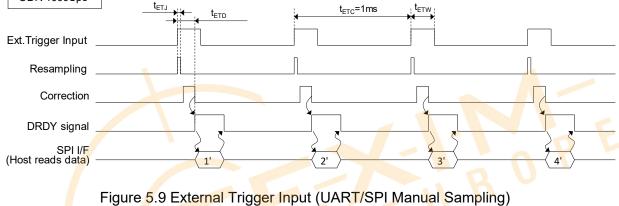
• For all other modes:

When External Trigger Input pin is asserted, the latest sampling data is set to each register and Data Ready signal is asserted. The Host should then read the sampling data synchronized with Data Ready signal.

Note) In case of External Trigger function usage please apply appropriate filter setting (**FILTER_SEL**) depending on the External Trigger period. Inappropriate filter setting may affect sensor noise performance.

The External Trigger Input Timing requirements and timing diagrams are shown in Figure 5.8, and Figure 5.9.





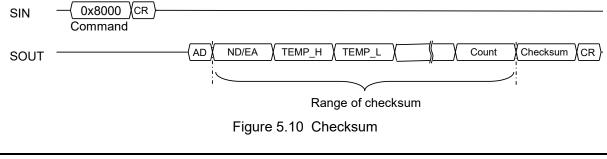
5.10 Checksum

A checksum can be appended to the response data during UART/SPI Burst mode or UART Auto sampling by enabling this function in **CHKSM_OUT** (BURST_CTRL [0x0C(W1)] bit 0).

The range of the data content for checksum is after the address byte (AD=0x80) of the response data (Figure 5.10). The checksum is calculated with a simple addition of the data content in units of 16-bit, and the resulting sum is truncated to 16-bits and appended as checksum just before delimiter byte (CR=0x0D).

For example:

Because the sum is "611B4" for the response data stream of "FE01 C455 4000 0052 33C0 0043 7BC8 004A 2608 FD73 3AA0 FF75 4C30 1F53 8FD0 0600 0014", the checksum is "11B4":



5.11 Automatic Start (For UART Auto Sampling Only)

Automatic Start function is designed to be used in conjunction with the UART Auto sampling. When the power is supplied or the accelerometer is restart/reset, it allows the device to automatically enter Sampling mode after completing internal initialization. Please refer to Figure 5.3 for the state transition.

Follow the procedures below to enable the Automatic Start function:

- Write a "1" to both UART_AUTO (bit [0]) and AUTO_START (bit [1]) of UART_CTRL [0x08(W1)].
- Store the current register settings to non-volatile memory by writing a "1" to FLASH_BACKUP (GLOB_CMD [0x0A(W1)] bit [3]). After completion of the FLASH_BACKUP command, confirm the results by FLASH_BU_ERR (DIAG_STAT [0x04(W0)] bit [0]).
- The Accelerometer will automatically enter Sampling Mode after the power supply is cycled, or a hardware reset, or a software reset command is executed.

Follow the procedures below to disable this function.

- After entering sampling mode with automatic start, write "01" to **MODE_CMD** of register: MODE_CTRL [0x02 (W0)], bit [9: 8] and enter the configuration mode
- Write "0" to AUTO_START of register: UART_CTRL [0x08 (W1)], bit [1].
- The subsequent steps are the same as above. Please store the register setting to nonvolatile memory and restart or reset the accelerometer.

5.12 Bias Offset

This function adjusts acceleration bias of X, Y, Z axis. The user specified offset is applied to the measured acceleration value before being sent out the serial interface.

Set the bias offset value to the registers: XA_OFFSET [0x2F - 0x2C (W1)], YA_OFFSET [0x33 - 0x30 (W1)], ZA_OFFSET [0x37 - 0x34 (W1)]. The adjustment range is -15 G to +15 G. The data format is the same as the output format of register: ACCL [0x3A - 0x30 (W0)]. Both the X, Y, and Z axes are set to "0" when shipped.

5.13 Tilt Output / Combination Output

The device can be configured to output tilt angle by register setting. The tilt angle is calculated from the measured gravitational acceleration vector. The calculation formulas are as follows.

 $\theta = \operatorname{asinG}[rad]$

The device is configurable to select the measurement output type for each axis to be either acceleration or tilt angle. The measurement output type is selected with **OUTPUT_SEL_*** of register: SIG_CTRL [0x00 (W1)], bit [7: 5].

When both acceleration and tilt angle is outputting at the same time, set **OUTPUT_SEL** to "Tilt angle" and read register: ACCL [0x3A - 0x30 (W0)] and register: TILT [0x46 - 0x3C (W0)] in normal mode.

5.14 Intermittent Measurement for Total Current Reduction

This explains how to realize intermittent measurement for reducing the device current consumption. The user can realize the intermittent measuremet by one of the methods below.

(1) Method of using a sleep mode

5. Basic Operation

(2) Method of switching the device power directly on and off

Table 5.1 shows a summary of some essential items and characteristics.

	(1) Using sleep mode	(2) Device power on and off
Switching method	Controlling a register and an EXT pin.	Switching the M-A352 power directly on and off
Current consumption at standby	1.3 mA (typ.)	0 mA
Wakeup time	16 msec (Max.)	900 msec (Max.)
Advantage	Short wakeup time from sleep mode to sampling mode	Minimum current consumption at standby (power off)
Disadvantage	-	Necessity for design considerations to correctly handle floating device interface pins, or unpowered pins during standby mode (power off) and transition current at wakeup (power on)
Example of intended use	Event-driven measurement	Occasional measurement and long standby (power off) time

 Table 5.1 Summary of Intermittent Measurement Characteristics and Parameters

Note) When returning to sampling mode, current consumption increases from a low level to the typical current at sampling mode. This causes an increase in internal heating of the device resulting in a transitional increase in temperature compensation errors.

Note) The extent of the errors depends on many variables such as standby time, environment conditions, etc, therefore, the user should evaluate carefully these effects when used for strict and high precision measurement scenarios.

Method of using sleep mode

The sleep mode function can be enabled by register setting. When shifting to sleep mode, internal circuit operation stops and current consumption during standby mode can be reduced to 1.3 mA (typ.). Wakeup time from sleep mode to sampling mode can be shorter than that from power on to start time (reduced from 900 msec to 16 msec).

Put the operation mode from configuration mode into sleep mode by writing "11" to **MODE_CMD** (MODE_CTRL[0x02(W0)], bit[9:8]). The device can wake up from sleep mode to configuration mode in Sleep Wake-up Time by detecting an edge trigger on the EXT pin. Timing sequence from configuration mode to sleep mode and vice versa are shown in Figure 5.11.

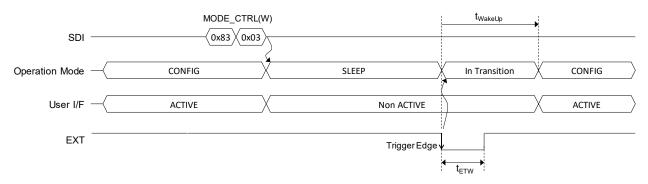


Figure 5.11 Timing Sequence from Configuration mode to Sleep mode and vice versa

Method of switching the device power directly on and off

When the device power is directly switched on and off, the current consumption during standby mode can be 0 mA. Wakeup time from standby to sampling mode is exactly the same as that from power on to start time (900 msec). Please refer to "5.2 Operation Mode" for timing sequence from the power on to sampling mode.

Note) The communication interface pins shown in Table 2.6 will be un-powered during standby (the device power being off), and transition current will appear at wakeup time (device power on). The system interface to the device may need additional design considerations to mitigate the effects, i.e. an unpowered device input pin appears as a short circuit to GND to the host system or when the device is powered on before the system interface to these pins are driven (floating input).

5.15 Measurement with Reduced Noise Floor Condition

The device can be configured to output data with a Reduced noise floor condition by register setting. Check the noise density characteristics shown in Figures 4.1-4.2 for standard noise floor level and reduced noise floor level.

Note) If the setting for the noise floor condition is switched from the standard condition to the reduced condition, current consumption during sampling increases from 13.2 mA typ. to 16.2 mA typ.

Follow the procedures below to select a Reduced noise floor condition,

- Set MESMOD_SEL (SIG_CTRL[0x00(W1)], bit[4]) to "1: Enable".
- Store the current register settings to non-volatile memory by writing a "1" to FLASH_BACKUP (GLOB_CMD [0x0A(W1)], bit [3]). After completion of the FLASH_BACKUP command, confirm the results by FLASH_BU_ERR (DIAG_STAT [0x04(W0)], bit [0]) to be "0: No error".
- The Reduced noise floor condition will be applied after the power supply is cycled, or a hardware reset or a software reset command is executed. The status can be checked by MESMOD _STAT (GLOB_CMD[0x0A (W1)], bit[12]) to be "1: Reduced noise floor condition".
- Put the operation mode from configuration mode into sampling mode by writing "01" to MODE_CMD (MODE_CTRL[0x02(W0)], bit[9:8]) to start measurement with the Reduced noise floor condition.

Follow the procedures below to return to Standard noise floor .

- Set **MESMOD_SEL** (SIG_CTRL[0x00(W1)], bit[4]) to "0: Standard noise floor condition".
- The subsequent steps are the same as above. Please store the register setting to nonvolatile memory and restart or reset the device.

5.16 Bias Temperature Shock Compensation

The device is equipped with a bias stabilization function against thermal shock. The factory setting is set to "1: enable" for this function. When enabled, the time period for bias stabilization after power on is reduced, and the bias errors due to an environmental temperature change are reduced.

Note) This function when enabled may increase errors in estimation of inertial position when state estimation filters such as a Kalman filter are used for inertial navigation etc.

When data without bias temperature shock compensation is preferred, disable this function by setting **TEMP_STABIL** (SIG_CTRL[0x00(W1)], bit[2]) to "0: Disable".

5.17 FILTER

The device has a programmable internal FIR filter. The intermediate sensor signal at 4k sps is processed by the FIR filter and decimated according to the output timing and sent out the serial interface. The number of TAPs and a cutoff frequency can be set with the FILTER_CTRL [0x06(W1)] register.

5.17.1 FIR Kaiser Filter

Filter parameters correspond to the Kaiser window parameters.

The number of TAPs can be set to 64, 128, or 512, and the cutoff frequency Fc can be selected according to the output sample rate. Figures 5.12 to 5.15 show the typical characteristic of the filters.

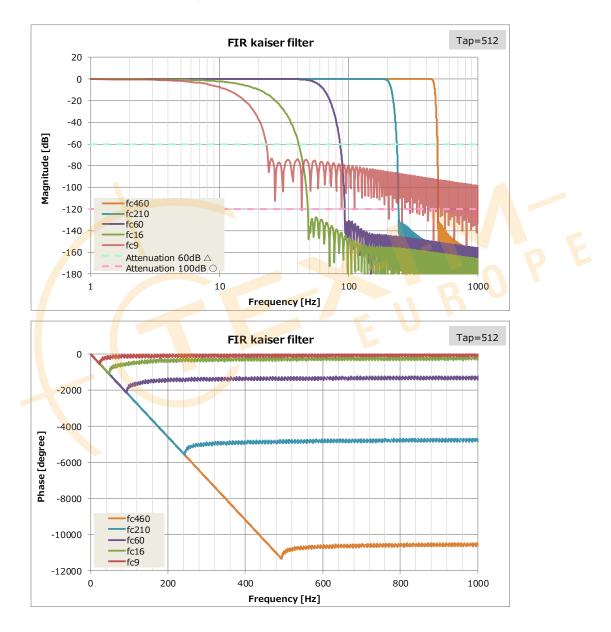


Figure 5.12 FIR Kaiser Filter Characteristic (512 taps)

5. Basic Operation

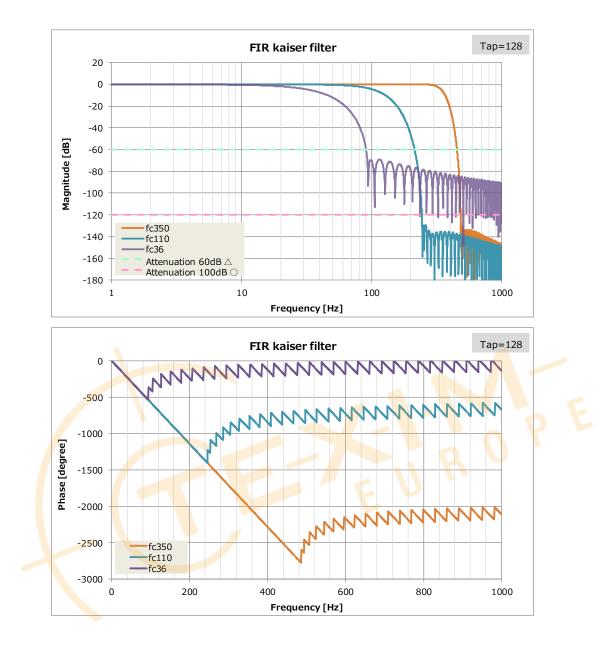


Figure 5.13 FIR Kaiser Filter Characteristic (128 taps)

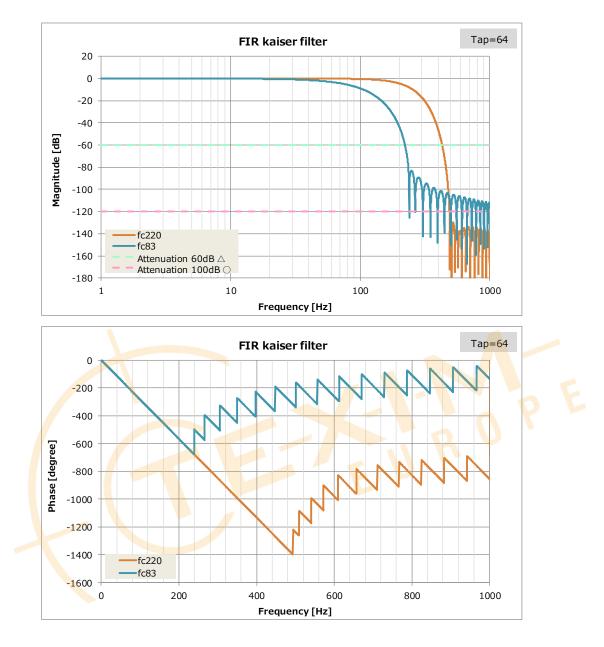


Figure 5.14 FIR Kaiser Filter Characteristic (64 taps)

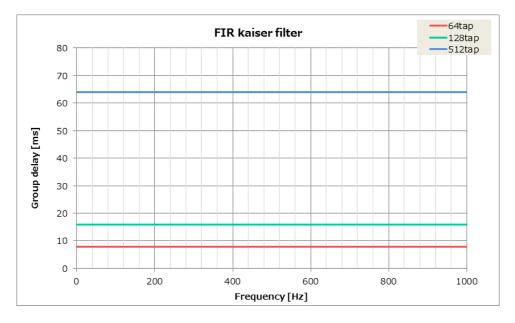


Figure 5.14 FIR Kaiser Filter Characteristic – Group Delay

5.17.2 User Defined FIR Filter

The FIR filter can be arbitrarily defined by properly setting filter coefficients in the registers: FIR_UCMD [0x16 (W1)], FIR_UDATA [0x18 (W1)], FIR_UADDR [0x1A (W1)], and set **FILTER_SEL** of register: FILTER_CTRL [0x06(W1)] to "user defined FIR filter".

Follow the procedures below to program the user defined FIR filter.

• Register Programming Preparation

Set the filter coefficient value using signed 32 bit fixed point number with decimal point after bit [31]. For example, if the coefficient value in decimal form is 0.2195378928, the corresponding filter coefficient value in signed 32 bit fixed point form is 0.2195378928^{231} \Rightarrow 0x1C19D153.

Table 5.2 shows the address ranges for the filter coefficients, and Figure 5.16 shows a N-tap FIR filter architecture and a coefficient memory map. The start address is common to each tap number and is at 0x0800. No specific values are set in memory at the factory shipment.

Тар	Coefficient Address Range			
4	0x0800-0x080F			
64	0x0800-0x08FF			
128	0x0800-0x09FF			
512	0x0800-0x0FFF			



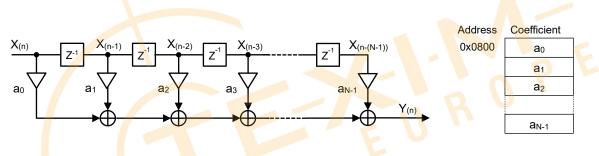


Figure 5.16 N-tap FIR Filter Architecture and Coefficient Memory Map

Register Control (Write)

Set the filter coefficient address in register: FIR_UADDR [0x1B, 0x1A (W1)] and set the filter coefficient value in **FIR_UDATA** of register: FIR_UDATA [0x18 (W1)].

Set **FIR_UCMD** of register: FIR_UCMD [0x16 (W1)], bit [1: 0] to write the coefficient value. Next coefficient value can be set after waiting until the **FIR_UCMD** of registeris to be "00: execution complete"

After the byte has completed writing, the address is automatically incremented by 1, so continuous programming of coefficients are possible without requiring additional address settings.

For the coefficient value, set the upper byte to the upper address and the lower byte to the lower address. Figure 5.17 shows the write sequence.

Please specify the type of filter, TAP setting and cutoff frequency using **FILTER_SEL** in register: FILTER_CTRL[0x06 (W1)], bit [3:0]. When selecting the user defined FIR filter, the **FILTER_SEL** register must reflect the filter coefficient data that are programmed in the device.

5. Basic Operation

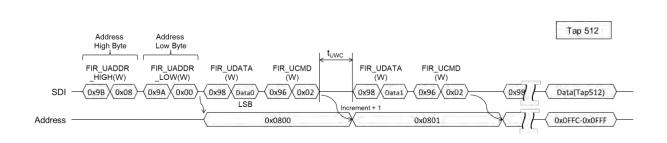
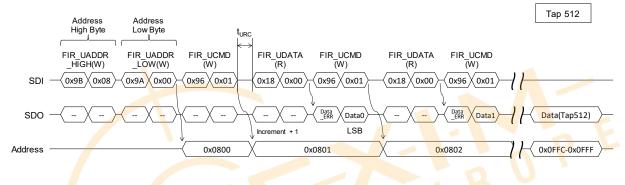


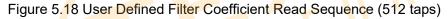
Figure 5.17 User Defined FIR Filter Coefficient Example Write Sequence (512 taps)

• Register Control (Read)

Set the filter coefficient address in register: FIR_UADDR [0x1B, 0x1A (W1)] and read the coefficient value using **FIR_UCMD** in register: FIR_UCMD [0x16 (W1)], bit [1: 0]. Next coefficient value can be read after waiting until the FIR_UCMD of registeris to be "00: execution complete"

The address is automatically incremented by 1, so continuous execution of read commands is possible without requiring additional address settings. Figure 5.18 shows the read sequence.





5.17.3 Notes For FIR Filter Usage

Transient response

As shown in Table 5.3, transient response data is generated according to the combination of the tap number and the data output rate when sampling is started.

In the case of internal timer trigger measurement, the acceleration value of register ACCL [0x3A - 0x30(W0)] is not updated during this period.

In the case of automatic measurement, the device starts outputting data after the transient response.

Table 5.3 Transient Response Data Based on Output Data Rate and Filter Tap

	64 Taps	128 Taps	512 Taps
1,000sps	15	31	127
500sps	7	15	63
200sps		7	31
100sps			15
50sps			7

• Supported Settings For Output Rate and Filter Cutoff Frequency

The host must set the cutoff frequency of the FIR filter and the output rate in proper combination to avoid aliasing.

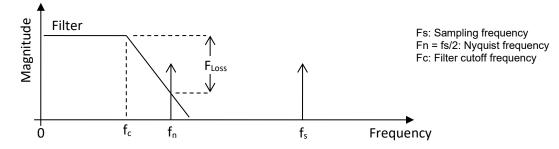


Figure 5.19 Anti-Aliasing Relationship Diagram

 Table 5.4 Supported Settings For Output Rate and Filter Cutoff Frequency

				SMPL_CTRL Register(Internal Timer Trigger)						
	Ton	Fc	Group	Output Data Rate						
_	Тар	FC	delay	50 Sps	100 Sps	200 Sps	500 Sps	1,000 Sps		
끤		460 <mark>H</mark> z		-	-	-		OK		
FILTER	512 Taps	210 Hz		-	-	-	OK	OK		
		60 Hz	63.875 ms	-	-	OK ^{*1}	OK	OK		
CTRL		16 Hz		-	OK	OK	OK	OK		
		9 Hz		*	*	*	*	*		
۲eg		350 <mark>H</mark> z			-	1- 1	-	OK		
Register	128 Taps	110 Hz 💆	15 <mark>.8</mark> 75 ms	-	-		OK	OK		
		36 H <mark>z</mark>		-	-	*	*	*		
	64 7000	220 Hz	7.875 ms	-	-	-	-	OK		
	64 Taps	83 Hz	1.0751115	-	-	-	*	*		

OK: F_{Loss} < -120 dB Recommended setting

* : F_{Loss} < -60 dB Although a possible setting, some decrease in measurement quality due to aliasing

 - : Fn < Fc Invalid setting. When using internal timer measurement, measurement data returns with error "0x64000000".

Note) These settings are valid when the user defined FIR filter function is used or the external trigger input function is active,

*1) The factory setting is Tap: 512, Fc: 60 Hz, ODR: 200 Hz

5.17.4 Long-Term Filter (HPF, LPF)

In addition to the FIR filter, this product has a simple filter for long-term measurement. This filter consists of a moving average at an output data rate. The number of taps can be set to a power of 2 in the range 2 to 4096.

LPF is a two-stage configuration with the set number of taps.

HPF consists of a single-stage configuration with the set number of taps and subtracting the moving average from the original data.

When using a long-term filter, set **FILT_EN** of register: LONGFILT_CTRL [0x1C (W1)], bit [0] to "1: valid" and select "LPF" or "HPF" in bit [1] **FILT_SEL**. Set the number of taps to TAP_SIZE of register: LONGFILT_TAP [0x1E (W1)].

Please note that transient response data is generated according to the combination of the tap size and a kind of filters (HPF/LPF) when sampling is started. Numbers of the transient response data for long period filters are shown in Table 5.5.

Table 5.5 Numbers of Transient Response Data for Long Period Filters

	Number of Transient Response Data		
HPF	TAP Size		
LPF	TAP Size * 2		

Note) The maximum output rate is limited to 500 Sps when long-term filter is used.

6. Digital Interface

This device has the following two external interfaces.

- (1) SPI interface
- (2) UART interface

The SPI interface and the UART interface have almost the same functions, except for Auto sampling function for the UART interface. No hardware pin configuration is necessary for SPI/UART selection since both interfaces are always active. Connect desired interface pins to SPI or UART interface.

Note) Connecting both SPI and UART at the same time is not supported and may result in malfunction of the device.

The registers inside the device are accessed via the SPI or UART interfaces.

In this document, data sent to the device is called a "Command" and data sent back in response to the command is called a "Response". There are two types of commands: write command and read command. The write command has no response. The write command always writes to the internal register in 8-bit words. The response to the read command, i.e. the data from the internal register, is always read in 16-bit words.

When reading from the registers, there is a burst mode in addition to the normal mode.

When the IMU output data rate is high (i.e. 1000sps), it may exceed the bandwidth of the host interface and cause the data transmission to be incorrect. In this case, the user must balance the transmission data rate and the bandwidth capability of the host interface.

Adjust the following settings accordingly to optimize the host interface bandwidth:

- For the UART, adjust the baud rate in **BAUD_RATE** (UART_CTRL [0x08(W1)] bit [9:8]).
- For the SPI, adjust the host side SPI clock frequency and SPI wait time.

Adjust the following settings accordingly to optimize the transmission data rate:

- The transmission data rate is affected by the data output rate setting in DOUT_RATE (SMPL_CTRL [0x04(W1)] bits [11:8]).
- The transmission data rate is also affected by the number of output bytes included in burst mode read transfer. The adjustment to the number of output bytes is in registers BURST_CTRL [0x0C(W1)].

Several concrete examples for setting the transmission data rate and host interface bandwidth are shown below:

(1) For UART Output:

- **BAUD_RATE** ="01" of UART_CTRL [0x08(W1)] bit [9,8]: 460800 baud
- UART_AUTO = "1" of UART_CTRL [0x08(W1)] bit [0]: UART Auto sampling
- DOUT_RATE = "0100" of SMPL_CTRL [0x04(W1)] bit [11:8]: 200Sps
- **BURST_CTRL** [0x0C(W1)] = "0x4702": TEMP, Acceleration, and COUNT output

(2) For SPI Output:

- SPI Interface Transmission Setting: f_{SCLK}=1MHz and t_{STALL}=24us for normal mode
- **DOUT_RATE** = "0100" of SMPL_CTRL [0x04(W1)] bit [11:8]: 200Sps
- **BURST_CTRL** [0x0C(W1)]= "0x4702" : TEMP, Acceleration, and COUNT output

6.1 SPI Interface

Table 6.1 shows the communication settings of SPI interface and Table 6.2 shows the SPI timing for normal mode.

Table 6.1 SPI Communication Settings

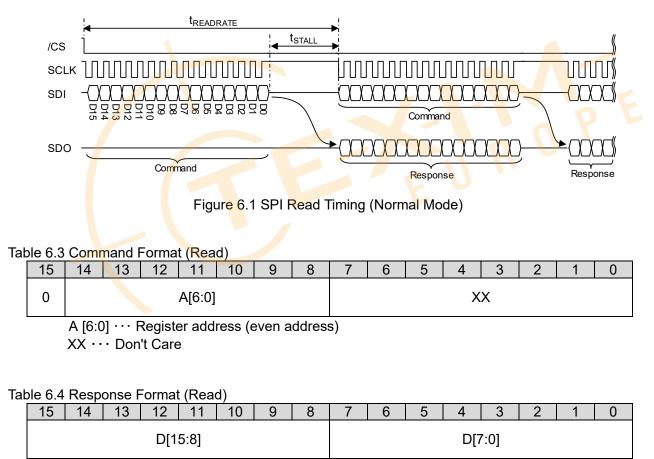
Parameter	Setting
Mode	Slave
Word length	16 bits
Phase	Rising edge
Polarity	Negative logic

Table 6.2 SPI Timing (Normal Mode)

Parameter	Minimum	Maximum	Unit	
f sclk	0.01	2.0	MHz	
t _{STALL}	20	-	μs	
t _{WRITERATE}	40	-	μs	
t _{READRATE}	40	-	μs	

6.1.1 SPI Read Timing (Normal Mode)

The response data to a read command, i.e. the data from the internal register, is always returned in 16bit words. The SPI interface supports sending the next command during the same bus cycle as receiving a response to the read command (full-duplex).



D[15:8] · · · Register read data (upper byte)

D[7:0] · · · Register read data (lower byte)

6.1.2 SPI Write Timing (Normal Mode)

A write command to a register has no response. Unlike register reading, registers are written in 8-bit words.

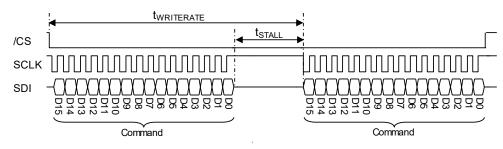


Figure 6.2 SPI Write Timing (Normal Mode)

Table 6.5 Command Format (Write)

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
1				A[6:0]							D[7	7:0]			

A [6:0] ··· Register address (even or odd number)

D [7:0] · · · Register write data

6.1.3 SPI Read Timing (Burst Mode)

Burst mode access of read data is supported using a "Burst Read Command" by writing 0x00 in **BURST_CMD** (BURST [0x00(W0)] bits[7:0]). In burst mode, ND flag/EA flag, temperature sensor value, 3-axis acceleration sensor value, etc. are consecutively sent as a response. The response format for the burst read output data is configured by register setting in BURST_CTRL [0x0C(W1)]. Please refer to 6.3 Data Packet Format for the response format.

Table 6.6 SP	Timina	(Burst Mode	١
	I IIIIIII		,

Paramet <mark>e</mark> r	Minimum	Maximum	Unit
fsclk	0.01	2.0	MHz
t _{STALL1}	45	-	μs
t _{STALL2}	0	-	μs
t _{READRATE2}	8	-	μs

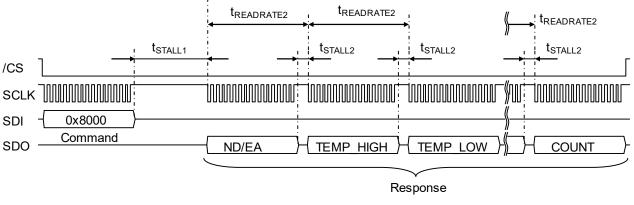


Figure 6.3 SPI Read Timing (Burst Mode)

6.2 UART Interface

Table 6.7 shows the supported UART communication settings and Figure 6.4 shows the UART bit format. Please refer to **BAUD_RATE** (UART_CTRL [0x08(W1)] bit[9:8]) for changing the baud rate setting.

Table	67	UART	Communication	Settings
IGNIO	U .,	0/ 11 11	Communication	ooungo

Parameter	Settings
Transfer rate	115.2kbps/ 230.4kbps/ 460.8kbps
Start	1 bit
Data	8 bits
Stop	1 bit
Parity	None
Delimiter	CR(0x0D)

TX,RX



Data



For the UART interface, a delimiter (1 byte) is placed at the end of each command (by the host) and response (by the IMU). In addition for responses, the address (1 byte) specified by the command is added (by the IMU) to the beginning of the response.

Table 6.8 and Table 6.9 shows the timing of UART.

		Manual S	Sampling		Auto S	ompling	
Pa <mark>r</mark> ameter	Norma	al Mod <mark>e</mark>	Burst	Mode	Auto S	ampling	Unit
	Minimum	Maximum	Minimum	M <mark>axi</mark> mum	Minimum	Maximum	
t _{sTALL} (11 <mark>5</mark> .2kbps)	-	25	-	45	-	- *2	μs
t _{stall} (23 <mark>0.4kbps)</mark>	-	25	-	45	-	- *2	μs
t _{stall} (460.8kbps)		25	-	45	-	- *2	μs
t _{WRITERATE} (115.2kbps)	660	-	-	-	660	-	μs
t _{wRITERATE} (230.4kbps)	350	-	-	-	350	-	μs
t _{WRITERATE} (460.8kbps)	200	-	-	-	200	-	μs
t _{READRATE} (115.2kbps)	660	-	*1	-	- *2	-	μs
t _{READRATE} (230.4kbps)	350	-	*1	-	- *2	-	μs
t _{READRATE} (460.8kbps)	200	-	*1	-	- *2	-	μs

*1) Please refer to Table 6.9.

*2) Register reading is not supported while in Sampling Mode with UART Auto Sampling enabled.

Table 6 OLIADT Tir	roquiromonto fo	r Durat Mada)
Table 6.9 UART Tir	i requirements io	Duist Mode)

Parameter	Burst Mode (minimum)	Unit
t _{READRATE} (115.2kbps)	660 + 86.8 * B	μs
t _{READRATE} (230.4kbps)	350 + 43.4 * B	μs
t _{READRATE} (460.8kbps)	200 + 21.7 * B	μs

B= Number of receive data bytes (AD: address and CR: delimiter is not included).

Example tREADRATE Calculation: BURST_CTRL[0x0C(W1)]: Set value 0x4702 B=18 byte for the above stated register setting $t_{READRATE}$ (460.8kbps) = 200 + (21.7 * 18) = 591(µs)

6.2.1 UART Read Timing (Normal Mode)

The response to the read command, i.e. the data from the internal register, is always returned 16-bit data at a time. The register address (AD) comes at the beginning of the response, for example, 0x02 for the MODE_CTRL [0x02(W0)] register.

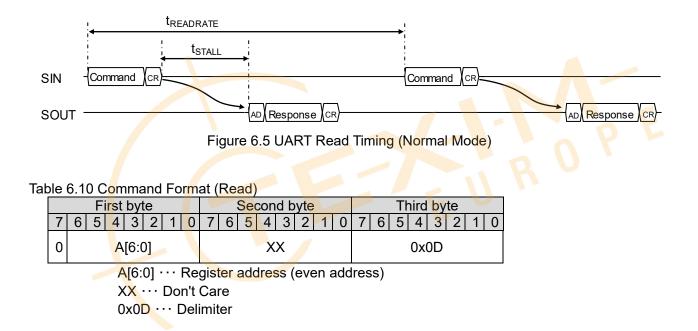
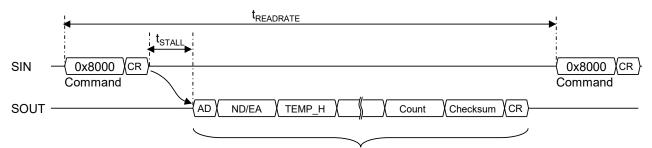


Table 6.11 Response Format (Read)

	First byte										Second byte									TI	hir	rd∣	by	te				Fourth byte								
	7	1 6 5 4 3 2 1 0 7 6 5 4 3 2 1									0	7	6	5	4	4	3	2	1	0	7	6		5	4	3	2	1	0							
	0			A	A[6:0] D[15:8] D[7:0] 0x0D																															
-					D[D[15	5:8 [[C] · 	··F	Rec eg	jist iste	er er	re	ad	da	s (e [.] ata ata ((up	pe	· by	te)																

6.2.2 UART Read Timing (Burst Mode)

Burst mode access of read data is supported using a "Burst Read Command" by writing 0x00 in **BURST_CMD** (BURST [0x00(W0)] bits[7:0]). In Burst Mode, ND/EA flag, temperature sensor value, 3-axis acceleration sensor value, etc. are consecutively sent as a response. The response format for the burst read output data is configured by register setting in BURST_CTRL [0x0C(W1)]. Please refer to 6.3 Data Packet Format for the response format.



Response

Figure 6.6 UART Read Timing (Burst Mode)

First byte 🔪										Second byte								Third byte							
7	7 6 5 4 3 2 1 0 7 6 5 4 3 2 1 0 7 6 5 4 3 2 1 0 7 6 5 4 3 2 1												0												
			0x	80							0x	00							0x	0D					
			0	x8	0	·• Е	Burs	st C	om	nma	and									/					
			0	x00	o •	··Е	Burs	st D	ata	1 O>	(00														
			0	x0I	D۰	••• [Deli	imit	er																

6.2.3 UART Write Timing

A write command to a register will have no response. Unlike register reading, registers are written in 8bit words.

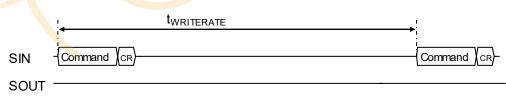


Figure 6.7 UART Write Timing

Table 6.13 Command Format (Write))
-----------------------------	--------	---

			Fi	irst	by	te			Second byte									Third byte							
ĺ	7	6	5	4	3	2	1	0	7	6	6 5 4 3 2 1 0							6	5	4	3	2	1	0	
1 A[6:0] D[7:0] 0x0D																									
-				D	-	0]	••	Re	gist	ter			``		en r	nun	nbe	er o	r oo	ı bb	nun	nbe	r)		

6.2.4 UART Auto Sampling Operation

When UART Auto sampling is active, all sensor outputs are sent as burst transfer automatically at the programmed output data rate without the request from the Host. For information about the response format, see 6.3 UART Data Packet Format. The response format for the burst read output data is configured by register setting in BURST_CTRL [0x0C(W1)].

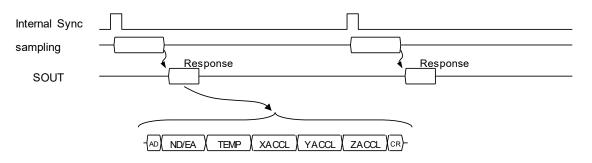


Figure 6.8 UART Auto Sampling Operation



6.3 Data Packet Format

The following table shows example of the data packet format sent to the host in the UART Burst Mode or UART Auto Sampling.

Table 6.14 UART Data Packet Format (UART Burst Mode / Auto Sampling) Example. BURST_CTRL[0x0C(W1)]=0xC703 (Burst Output, Temp, Acceleration, Counter, Checksum) SIG_CTRL[0x00(W1)]=0x8E04 (Output Mode: Acceleration, Bias stabilization: Enable)

Byte No.	Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
1	ADDRESS				0×	80			
2	ND	ND (Temp)	-	-	-	ND (XACCL)	ND (YACCL)	ND (ZACCL)	-
3	EA	-	-	-	XALARM ERR	YALARM ERR	ZALARM ERR	ALIASI ERR	EA
4	TEMP_ HIGH_H			-	TEMP_H	IGH [15:8]	-		
5	TEMP_ HIGH_L				TEMP_H	IIGH [7:0]			
6	TEMP LOW_H				TEMP_L	OW [15:8]			
7	TEMP_ LOW_L				TEMP_L	.OW [7:0]			
8	XACCL _HIGH_H				XACCL_H	IIGH [15:8]			
9	XACCL _HIGH_L				XACCL_I	HIGH [7:0]			
10	XACCL _LOW_H				XACCL_L	.OW [1 <mark>5:8</mark>]			E
11	XACCL _LOW_L				XACCL	LOW [7:0]		0	
12	YACCL _HIGH_H				YACCL_H	HIGH [15:8]	n		
13	YACCL _HIGH_L				YACCL _	HIGH [7:0]			
14	YACCL _LOW_H				YACCL_L	OW [15:8]			
15	YACCL LOW_L				YACCL_	LOW [7:0]			
16	ZACCL _HIGH_H				ZACCL_H	IIGH [15:8]			
17	ZACCL _HIGH_L				ZACCL_I	HIGH [7:0]			
18	ZACCL _LOW_H				ZACCL_L	OW [15:8]			
19	ZACCL _LOW_L				ZACCL _	LOW [7:0]			
20	COUNT_H				COUN	T [15:8]			
21	COUNT_L				COUN	IT [7:0]			
22	CHECKSUM_H				CHECKS	UM [15:8]			
23	CHECKSUM_L				CHECKS	SUM [7:0]			
24	CR				0x	0D			

Table 6.15 Data Packet Format (SPI BURST MODE) Example

BURST_CTRL[0x0C(W1)]=0xC703 (Burst Output, Temp, Acceleration, Counter, Checksum) SIG_CTRL[0x00(W1)]=0x8E04 (Output Mode : Acceleration, Bias stabilization: Enable)

Word No.	Bit15		Bit0
1		FLAG(ND/EA)	
2		TEMP_HIGH	
3		TEMP_LOW	
4		XACCL_HIGH	
5		XACCL_LOW	
6		YACCL _HIGH	
7		YACCL _LOW	
8		ZACCL _HIGH	
9		ZACCL_LOW	
10		COUNT	
11		CHECKSUM	



A host device (for example, a microcontroller) can control the Accelerometer by accessing the control registers inside the device.

The registers are accessed in this device using a WINDOW method. The prescribed window number is first written to **WINDOW_ID** of WIN_CTRL[0x7E(W0/W1)] bit [7:0], then the desired register address can be accessed. The WIN_CTRL [0x7E(W0/W1)] register can always be accessed without needing to set the window number.

During the Power-On Start-Up Time or the Reset Recovery time specified in the Table 2.4 Interface Specifications, all the register values are undefined because internal initialization is in progress. Ensure the device registers are only accessed after the Power-On Start-Up Time or the Reset Recovery time is over.

For information about the initial values of the control registers after internal initialization is finished, see the "Default" column in the Table 7.1. The control registers with ○ mark in the "Flash Backup" column can be saved to the non-volatile memory by the user, and the initial values after the power on will be the values read from the non-volatile memory. If the read out from the non-volatile memory fails, the **FLASH_ERR** (DIAG_STAT [0x04(W0)] bit[2]) is set to 1 (error).

Please ensure that the device is in the Configuration Mode before writing to registers. In the Sampling Mode, writing to registers is ignored **except** for the following cases.

- MODE_CTRL [0x02(W0)] bit [9:8] in **MODE_CMD**
- GLOB_CMD [0x0A(W1)] bit [7] in SOFT_RST
- WIN_CTRL [0x7E(W0/W1)] bit [7:0] in WINDOW_ID

While with the UART Auto sampling and Sampling Mode is active, register read access is not supported. Otherwise, the sampling data transmitted in the UART Auto sampling will be corrupted by the response data from the register read.

Each register is 16-bit wide and one address is assigned to every 8 bits. Registers are read in 16-bit words and are written in 8-bit words. The byte order of each 16-bit register is little endian, but the byte order of the 16-bit data transferred over the digital interface is big endian.

Table 7.1 shows the register map, and Section 7.1 through Section 7.30 describes the registers in detail.

The "-" sign in the register assignment table in Section 7.1 through Section 7.30 means "reserved".

Write a "0" to reserved bits during a write operation.

During a read operation, a reserved bit can return either 0 or 1 ("don't care").

Writing to a read-only register is prohibited.

NOTE) The explanation of the register notation MODE_CTRL [0x02(W0)] bit [9:8] is as follows:

- MODE_CTRL: Register name
- [0x02(W0)]: First number is the Register Address, (W0) means Window Number "0"
- bit[9:8]: Bits 9 to 8

Table 7.1 Register Map

Name	Window ID	Address	^(*3) Read Command 16bit Read	Write Command 8bitWrite	R/W	Flash Backup	Default	Function
BURST	0	0x00 0x01	-	0x80 -	- W	-	-	Burst mode
MODE_CTRL	0	0x02 0x03	0x02XX	- 0x83	- R/W	-	0x00 0x04	Operation mode control
DIAG_STAT	0	0x04 0x05	0x04XX	-	R	-	0x00 0x00	Diagnostic result
FLAG	0	0x06 0x07	0x06XX	-	R R	-	0x00 0x00	ND/EA flag
COUNT	0	0x0A 0x0B	0x0AXX	-	R R	-	0x00 0x00	Sampling count
TEMP_HIGH	0	0x0E 0x0F	0x0EXX	-	R R	-	0xFF 0xFF	Temperature sensor value High
TEMP_LOW	0	0x10 0x11	0x10XX	-	R R	-	0xFF 0xFF	Temperature sensor value Low
XACCL_HIGH	0	0x30 0x31	0x30XX	-	R R	-	0xFF 0xFF	X acceleration sensor value High
XACCL_LOW	0	0x32 0x33	0x32XX	-	R R	-	0xFF 0xFF	X acceleration sensor value Low
YACCL_HIGH	0	0x34 0x35	0x34XX	-	R R	-	0xFF 0xFF	Y acceleration sensor value High
YACCL_LOW	0	0x36 0x37	0x36XX	-	R	-	0xFF 0xFF	Y acceleration sensor value Low
ZACCL_HIGH	0	0x38 0x39	0x38XX	-	R R	-	0xFF 0xFF	Z acceleration sensor value High
ZACCL_LOW	0	0x3A 0x3B	0x3AXX	-	R	-	0xFF 0xFF	Z acceleration sensor value Low
XTILT_HIGH	0	0x3C 0x3D	0x3CXX	-	R R	- \	0xFF 0xFF	X Tilt sens <mark>o</mark> r Value High
XTILT_LOW	0	0x3E 0x3F	0x3EXX		R	-	0xFF 0xFF	X Tilt sensor Value Low
YTILT_HIGH	0	0x40 0x41	0x40XX	-	R R	K-	0xFF 0xFF	Y Tilt sensor Value High
YTILT_LOW	0	0x42 0x43	0x42XX	-	R R	-	0xFF 0xFF	Y Tilt sensor Value Low
ZTILT_HIGH	0	0x44 0x45	0x44XX	-	R R	-	0xFF 0xFF	Z Tilt sensor Value High
ZTILT_LOW	0	0x46 0x47	0x46XX	-	R R	-	0xFF 0xFF	Z Tilt sensor Value Low
SIG_CTRL	1	0x00 0x01	0x00XX	0x80 0x81	R/W R/W	0	0x04 0x8E	DataReady signal & polarity control
MSC_CTRL	1	0x02 0x03	0x02XX	0x82 0x83	R/W R/W	0	0x26 0x00	Other control
SMPL_CTRL	1	0x04 0x05	0x04XX	- 0x85	- R/W	0	0x00 0x04	Sampling control
FILTER_CTRL	1	0x06 0x07	0x06XX	0x86 -	R/W -	0	0x08 0x00	Filter control
UART_CTRL	1	0x08 0x09	0x08XX	0x88 0x89	R/W R/W	0	0x00 0x01	UART control
GLOB_CMD	1	0x0A 0x0B	0x0AXX	0x8A -	R/W R	-	0x00 0x00	System control
BURST_CTRL	1	0x0C 0x0D	0x0CXX	0x8C 0x8D	R/W R/W	0	0x02 0x47	Burst control
FIR_UCMD	1	0x16 0x17	0x16XX	0x96 -	R/W -	-	0x00 0x00	User FIR Filter control
FIR_UDATA	1	0x18 0x19	0x18XX	0x98 -	R/W R	-	0x00 0x00	User FIR Filter coefficient data

		0x1A		0x9A	R/W		0x00	User FIR Filter
FIR_UADDR	1	0x1A 0x1B	0x1AXX	0x9A 0x9B	R/W	-	0x00 0x08	coefficient Address
		0x1D		0x9C	R/W		0x00	Long period filter
LONGFILT_CTRL	1	0x10	0x1CXX	-	-	0	0x00	control
		0x1E		0x9E	R/W	-	0x0A	Long period filter tap
LONGFILT_TAP	1	0x1F	0x1EXX	-	-	0	0x00	number
		0x2C	0.00)()/	0xAC	R/W	0	0x00	X acceleration offset
OFFSET_XA_HIGH	1	0x2D	0x2CXX	0xAD	R/W	0	0x00	value High
	1	0x2E	0x2EXX	0xAE	R/W	0	0x00	X acceleration offset
OFFSET_XA_LOW	I	0x2F	UXZEAA	0xAF	R/W	0	0x00	value Low
OFFSET_YA_HIGH	1	0x30	0x30XX	0xB0	R/W	0	0x00	Y acceleration offset
OFFSET_TA_HIGH		0x31	023022	0xB1	R/W	0	0x00	value High
OFFSET_YA_LOW	1	0x32	0x32XX	0xB2	R/W	0	0x00	Y acceleration offset
		0x33	0,02///	0xB3	R/W	0	0x00	value Low
OFFSET_ZA_HIGH	1	0x34	0x34XX	0xB4	R/W	0	0x00	Z acceleration offset
	1	0x35	0704777	0xB5	R/W	0	0x00	value High
OFFSET_ZA_LOW	1	0x36	0x36XX	0xB6	R/W	0	0x00	Z acceleration offset
		0x37	0,00,0,0	0xB7	R/W	<u> </u>	0x00	value Low
XALARM	1	0x46	0x46XX	0xC6	R/W	0	0xF1	X acceleration alarm
		0x47	0,10,0,	0xC7	R/W	Ŭ	0x0F	
YALARM	1	0x48	0x48XX	0xC8	R/W	0	0xF1	Y acceleration alarm
		0x49		0xC9	R/W		0x0F	
ZALARM	1	0x4A	0x4AXX	0xCA	R/W	0	0xF1	Z acceleration alarm
		0x4B		0xCB	R/W		0x0F	
PROD_ID1	1	0x6A	0x6AXX	-	R	-	0x41	Product ID 1
		0x6B		-	R		0x33	
PROD ID2	1	0x6C	0x6CXX	-	R	-	0x35	Product ID 2
_		0x6D		-	R		0x32	
PROD_ID3	1	0x6E	0x6EXX	-	R		0x41	Product ID 3
_		0x6F		-	R		0x44	
PROD_ID4	1	0x70 0x71	0x70XX		R R		0x31 0x30	Product ID 4
		0x71		-	R		0x30	
VERSION	1	0x72 0x73	0x72XX	-	R		(*1)	Firmware version
		0x73		-	R			
SERIAL_NUM1	1	0x74	0x74XX		R	S - V	(*2)	Serial Number 1
		0x76		-	R			
SERIAL_NUM2	1	0x70	0x76XX	-	R	-		Serial Number 2
		0x77		_	R			
SERIAL_NUM3	1	0x70	0x78XX	-	R	-		Serial Number 3
		0x7A		_	R			
SERIAL_NUM4	1	0x7B	0x7AXX	_	R	-		Serial Number 4
	0,1	0x7E	0x7EXX	0xFE	R/W		0x00	Register Window
WIN CTRL								

 * 1) It depends on the version of the installed firmware.

* 2) It is determined by each individual serial number.

* 3) Lower byte XX: Do not care

7.1 BURST Register (Window 0)

Addr (Hex)	Bit15		Bit8	R/W
0x01		-		-
Addr (Hex)	Bit7		Bit0	R/W
0x00		BURST_CMD		W
bit[7:0]	BURST	CMD		

A burst mode read operation is initiated by writing 0x00 in **BURST_CMD** of this register.

NOTE) The data transmission format is described in 6.1.3 SPI Read Timing (Burst Mode) and

6.2.2 UART Read Timing (Burst Mode). Also refer to 6.3 Data Packet Format. The output data can be selected by setting BURST_CTRL [0x0C(W1)].

7.2 MODE_CTRL Register (Window 0)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x03	-		-	-	MC _S1	DE TAT	MODE	_CMD	R/W *1

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x02	-	·			-		K	-	-

*1) MODE_STAT is read-only.

bit[11:10] MODE_STAT

This read-only status bit shows the current operation mode.

- 00: Sampling Mode
- 01: Configuration mode
- 10: Sleep Mode
- 11: (Not Used)

bit[9:8] MODE_CMD

Executes commands related to the operation mode.

- 00: Execute Complete.
- 01: Go to the Sampling Mode. After the mode transition is completed, the bits automatically goes back to "00".
- 10: Go to the Configuration Mode. After the mode transition is completed, the bits automatically goes back to "00".
- 11: Go to the Sleep Mode. After the mode transition is completed, the bits automatically goes back to "00".

7.3 DIAG_STAT Register (Window 0)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x05	ACC_VS _ERR	ACC_X _ERR	ACC_Y _ERR	ACC_Z _ERR	SEI _EF	NS RR	TEMP _ERR	VDD _ERR	R

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x04		HARD _ERR		SPI _OVF	UART _OVF	FLASH _ERR	ACC_ERR _ALL	FLASH_ BU_ERR	R

Note) When the host reads the diagnosis result, all the results (including the EA flag in the FLAG register) will be cleared to 0.

bit[15] ACC_VES_ERR (ACC VEctorSynthesis ERRor)

```
Shows the execution result of vector composite value of acceleration three axes in ACC_TEST of MSC_CTRL [0x02 (W1)], bit [10].
```

1: Error occurred

0: No error

If this error occurs, acceleration sensor is faulty.

bit[14] ACC_X_ERR

Shows the result of X axis acceleration sensor operation check in ACC_TEST of

MSC_CTRL [0x02 (W1)], bit [10].

1: Error occurred

0: No error

If this error occurs, X axis acceleration sensor has failed (operation stop)

bit[13] ACC_Y_ERR

Shows the result of Y axis acceleration sensor operation check in ACC_TEST of

MSC_CTRL [0x02 (W1)], bit [10].

1: Error occurred

0: No <mark>e</mark>rror

If this error occurs, Y axis acceleration sensor has failed (operation stop)

bit[12] ACC_Z_ERR

Shows the result of Z axis acceleration sensor operation check in **ACC_TEST** of MSC_CTRL [0x02 (W1)], bit [10].

1: Error occurred

0: No error

If this error occurs, Z axis acceleration sensor has failed (operation stop)

bit[11:10]SENS_ERR (SENSitivity ERRor)

Shows the execution result of **SENS_TEST** (Sensitivity Test) of MSC_CTRL [0x02 (W1)], bit [14:12].

- 11 : Not used
- 10 : Unable to be determined
- 01 : Error occurred
- 00 : No error
- If this error occurs, acceleration sensor is faulty.

bit[9] TEMP_ERR

Shows the execution result of **TEMP_TEST** (Temp Sensor Check) of MSC_CTRL [0x02 (W1)], bit [9].

1: Error occurred

0: No error

If this error occurs, temperature sensor is faulty.

bit[8] VDD_ERR

Shows the execution result of **VDD_TEST** (Power Supply Voltage Check) of MSC_CTRL [0x02 (W1)], bit [8].

1: Error occurred

0: No error

If this error occurs, Check whether the power supply voltage level is within the specified range. **bit**[7:5] **HARD_ERR**

Shows the result of the hardware check at startup.

Other than 00: Error occurred

00 : No error

When this error occurs, it indicates the device is faulty.

bit[4] SPI_OVF (SPI OVer Flow)

Shows an error occurred if the device received too many commands from the SPI interface in short period of time.

1: Error occurred

0: No error

When this error occurs, review the SPI command transmission interval and the SPI clock setting.

bit[3] UART_OVF (UART OVer Flow)

Shows an error occurred if the data transmission rate is faster than the UART baud rate.

1: Error occurred

0: No error

When this error occurs, review the settings for the baud rate (register: UART_CTRL[0x08(W1)], bit[9:8]), data output rate (register: SMPL_CTRL[0x04(W1)],bit[11:8]), UART Burst Mode / Auto sampling (register: BURST_CTRL[0x0C(W1)]) in combination.

bit[2] FLASH_ERR

Shows the result of FLASH_TEST of MSC_CTRL [0x02(W1)] bit[11].

- 1: Error occurred
- 0: No error

This error indicates a failure occurred when reading data out from the non-volatile memory.

bit[1] ACC_ERR_ALL (ACCTest ERRor All)

Shows the logical sum of bit [15:12] of this register.

1: Error occurred

0: No error

bit[0] FLASH_BU_ERR (FLASH BackUp ERRor)

Shows the result of **FLASH_BACKUP** of GLOB_CMD [0x0A(W1)] bit [3].

- 1: Err<mark>o</mark>r occurred
- 0: No<mark>e</mark>rror

7.4 FLAG(ND/EA) Register (Window 0)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x07	ND (Temp)	-	-	-	ND (XACCL)	ND (YACCL)	ND (ZACCL)	-	R

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x06	-	-	-	XALARM _ERR	YALARM _ERR	ZALARM _ERR	ALIASI _ERR	EA	R

Note) ALARM_ERR flags are cleared to "0" by reading this register.

Note) The EA flag is cleared to "0" by reading the DIAG_STAT register.

Note) The ALIASI_ERR flag is updated when writing to the SMPL_CTRL or FILTER_CTRL register.

bit[15] ND(New Data) flag (Temperature)

When new measurement data is set in temperature register: TEMP_HIGH [0x0E (W0)], this bit is set to "1". This bit is reset to "0" reading by the temperature register.

bit[11:9] ND(New Data) flag (Acceleration)

When new measurement data is set in acceleration register: XACCL_HIGH[0x30(W0)], YACCL_HIGH[0x34(W0)], ZACCL_HIGH[0x38(W0)], this bit is set to "1". This bit is reset to "0" by reading the temperature register.

bit[4] XALARM_ERR(XAcc_ALARM_ERRor)

This bit indicates when the acceleration exceeds the value set in register: XA_ALARM[0x47-0x46(W1)] in the X axis during measurement.

1: detection

0: no detection

bit[3] YALARM_ERR(YAcc_ALARM_ERRor)

This bit indicates when the acceleration exceeds the value set in register: YA_ALARM[0x49-0x48(W1)] in the Y axis during measurement.

1: detection

0: no detection

bit[2] ZALARM_ERR(ZAcc_ALARM_ERRor)

This bit indicates when the acceleration exceeds the value set in register: ZA_ALARM[0x4B-0x4A(W1)] in the Z axis during measurement.

1: detection

0: no detection

bit[1] ALIASI_ERR(ALIASIng_ERRor)

This bit indicates the validation check of the combination setting of the output rate in register: SMPL_CTRL[0x04(W1)],bit[11:8] and filter cutoff frequency in register: FILTER_CTRL[0x06 (W1)],bit[3:0].

1: Abnormal Setting

0: Normal Setting

bit[0] EA(All Error) flag

When at least one failure is found in the diagnostic result (DIAG_STAT [0x04(W0)]), this bit is set to "1"(failure occurred). This bit is reset to "0" by reading the DIAG_STAT register.

1: Failure occurred

0: No <mark>F</mark>ailure

7.5 COUNT Register (Window 0)

Addr (Hex)	Bit15		Bit0	R/W
0x0A		COUNT		R

bit[15:0] COUNT

This register returns the sampling count value of the internal A/D converter.

Note) The time unit of the sampling counter value represents 250 µs/count.

Example: If the data output rate equals 1000Sps, the counter value sequence is 4,8,12, ..., 0xFFFC, 0, 4,

7.6 TEMP Register (Window 0)

Addr (Hex)	Bit15		Bit0	R/W
0x0E		TEMP_HIGH		R
0x10		TEMP_LOW		R

bit[15:0] Temperature sensor output data

The internal temperature sensor value can be read from this register. The output data format is 32-bit two's complement format.

Please refer to the below formula for conversion to temperature in centigrade. Please refer to Table 2.3 Sensor Specification for the scale factor value.

The reference value in this register is for the temperature correction. There is no guarantee that the value provides the absolute value of the internal temperature.

T [°C]= SF * a + 34.987

SF: Scale Factor A: Temperature sensor output data (decimal)

7.7 ACCL Register (Window 0)

Addr (Hex)	Bit15	Bit	t0	R/W
0x30		XACCL_HIGH		R
0x32		XACCL_LOW	D	R
0x34		YACCL_HIGH		R
0x36		YACCL_LOW		R
0x38		ZACCL_HIGH		R
0x3A		ZACCL_LOW		R

bit[15:0] Acceleration sensor output data

These registers contain the 3-axis acceleration data for X, Y, and Z. Register: SIG_CTRL [0x00 (W1)] provides the output mode selection OUTPUT_SEL of bit [7: 5] to specify the acceleration data as either "acceleration" or "Tilt angle".

The output data format Unit [G] 32-bit two's complement format bit31 : sign bit30~24 : integer bit23~0 : decimal

Note) When the combination of output rate and filter cutoff frequency is "abnormal setting", reading acceleration sensor value responds with error code "0x64000000"

Note) When the acceleration value exceeds the preset threshold value, reading acceleration value responds with the threshold value. For example, if the preset threshold values are set to +15 G and -15 G, the corresponding response is "0x0F000000" for +15 G or more, and "0xF1000000" for -15 G or less.

7.8 TILT Register (Window 0)

Addr (Hex)	Bit15		Bit0	R/W			
0x3C		XTILT_HIGH		R			
0x3E		XTILT_LOW					
0x40		YTILT_HIGH					
0x42		YTILT_LOW		R			
0x44		ZTILT_HIGH		R			
0x46		ZTILT_LOW		R			

bit[15:0] Tilt sensor output data

These registers contain the 3-axis Tilt angle data for X, Y, and Z.

Register: SIG_CTRL [0x00 (W1)] The tilt angle is output only when the output mode selection OUTPUT_SEL of bit [7: 5] is set to "tilt angle".

The output data format Unit [radian] 32-bit two's complement format bit31 : sign bit30~29 : integer bit28~0 : decimal

Note) When the combination of output rate and filter cutoff frequency is "abnormal setting", reading tilt angle sensor value responds with error code "0x64000000"

Note) When the tilt angle value exceeds the dynamic range (\pm 60 deg), reading tilt angle value responds with the value of +60 deg or -60 deg. For example, the corresponding response is "0x2182A470" for +60 deg or more, and "0xDE7D5B90" for -60 deg or less.

7.9 SIG_CTRL Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	/ Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x01	ND_EN (Temp)			-	ND_EN (XACCL)	ND_EN (YACCL)	ND_EN (ZACCL)	-	R/W

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x00	OUTPUT_ SEL_X	OUTPUT_ SEL_Y	OUTPUT_ SEL_Z	MESMOD _SEL	-	TEMP_ STABIL	-	-	R/W

bit[15] ND_EN (Temp)

Enables or disables the temperature sensor ND flags in FLAG [0x06(W0)] bit [15].

1: Enable

0: Disable

bit[11] ND_EN (X Acceleration sensor)

Enables or disables the X Acceleration sensor ND flags in FLAG [0x06(W0)] bit [11].

1: Enable

0: Disable

bit[10] ND_EN (Y Acceleration sensor)

Enables or disables the Y Acceleration sensor ND flags in FLAG [0x06(W0)] bit [10].

- 1: Enable
- 0: Disable

bit[9] ND_EN (Z Acceleration sensor)

Enables or disables the Z Acceleration sensor ND flags in FLAG [0x06(W0)] bit [9]. 1: Enable

0: Disable

bit[7] OUTPUT_SEL_X

Sets the output mode on the X axis.

- 1: Tilt angle
- 0: Acceleration

bit[6] OUTPUT_SEL_Y

Sets the output mode on the Y axis.

- 1: Tilt angle
- 0: Acceleration

bit[5] OUTPUT_SEL_Z

Sets the output mode on the Z axis.

- 1: Tilt angle
- 0: Acceleration

bit[4] MESMOD_SEL

Sets the measurement condition.

1: Reduced noise floor condition

0: Standard noise floor condition

When **MESMOD_SEL** is set, the device can operate with the set measurement condition after completing internal initialization after powered on or a reset.

Write to this **MESMOD_SEL** bit. Then execute FLASH_BACKUP of GLOB_CMD [0x0A(W1)] bit [3] to preserve the current register settings. Read the **MESMOD_STAT** of register:

GLOB_CMD[0x0A (W1)],bit[12] to check the current setting of measurement condition.

bit[2] TEMP_STABIL

Bias stabilization against thermal shock.

- 1: Enable
- 0: Disable

7.10 MSC_CTRL Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x03	-	Z_SENS _TEST	Y_SENS _TEST	X_SENS _TEST	FLASH _TEST	ACC _TEST	TEMP _TEST	VDD _TEST	R/W

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x02	-	EXT _SEL	EXT _POL	-	-	DRDY _ON	DRDY _POL	-	R/W

Note) Although ACC_TEST, TEMP_TEST, and VDD_TEST can be executed at the same time, other tests cannot be executed at the same time.

When executing them in succession, confirm the execution of the previous command is finished by waiting until the bit changes from "1" to "0" and then execute the next command.

bit[14] Z_SENS_TEST

Write "1" to execute the self test to check if the Z axis accelerometer sensitivity is working properly. The read value of the bit is "1" during the test and "0" after the test is completed. After writing "1" to this bit, wait until this bit goes back to "0" and then read the **SENS_ERR** of DIAG STAT [0x04(W0)] bit [11:10] to check the result.

bit[13] Y_SENS_TEST

Write "1" to execute the self test to check if the Y axis accelerometer sensitivity is working properly. The read value of the bit is "1" during the test and "0" after the test is completed. After

writing "1" to this bit, wait until this bit goes back to "0" and then read the **SENS_ERR** of DIAG_STAT [0x04(W0)] bit [11:10] to check the result.

bit[12] X_SENS_TEST

Write "1" to execute the self test to check if the X axis accelerometer sensitivity is working properly. The read value of the bit is "1" during the test and "0" after the test is completed. After writing "1" to this bit, wait until this bit goes back to "0" and then read the **SENS_ERR** of DIAG STAT [0x04(W0)] bit [11:10] to check the result.

bit[11] FLASH_TEST

Write "1" to execute the data consistency test for the non-volatile memory. The read value of the bit is "1" during the test and "0" after the test is completed. After writing "1" to this bit, wait until this bit goes back to "0" and then read the **FLASH_ERR** of DIAG_STAT [0x04(W0)] bit [2] to check the result.

bit[10] ACC_TEST

Write "1" to execute the self test to check if the accelerometer is working properly. The read value of the bit is "1" during the test and "0" after the test is completed. After writing "1" to this bit, wait until this bit goes back to "0" and then read the **ACC_ERR_ALL** of DIAG_STAT [0x04(W0)] bit [1] to check the results.

bit[9] TEMP_TEST

Write "1" to execute the self test to check if temperature sensor is working properly. The read value of the bit is "1" during the test and "0" after the test is completed. After writing "1" to this bit, wait until this bit goes back to "0" and then read the **TEMP_ERR** of DIAG_STAT [0x04(W0)] bit [9] to check the results.

bit[8] VDD_TEST

Write "1" to execute the self test to check if power supply voltage level is working properly. The read value of the bit is "1" during the test and "0" after the test is completed. After writing "1" to this bit, wait until this bit goes back to "0" and then read the **VDD_ERR** of DIAG_STAT [0x04(W0)] bit [8] to check the results.

bit[6] EXT_SEL

Select the function of the EXT terminal. To use the internal timer trigger, select "0".

1: External trigger input is enabled

0: External trigger input is disabled (internal timer trigger is enabled)

bit[5] EXT_POL

Selects the polarity of the External Counter Reset Input or External Trigger Input function. 1: Negative logic (falling edge)

0: Positive logic (rising edge)

bit[2] DRDY_ON

Selects the function of the DRDY terminal, when set to "1", Data Ready signal is output.

1: Data Ready Signal is enabled

0: Data Ready Signal is disabled

bit[1] DRDY_POL

Selects the polarity of the Data Ready signal when selected in **DRDY_ON** above.

1: Active High

0: Active Low

7.11 SMPL_CTRL Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x05	-	-	-	-		DOUT	_RATE		R/W

Addr (Hex)	Bit7		Bit0	R/W
0x04		-		-

bit[11:8] DOUT_RATE

Specifies the data output rate. To avoid aliasing, refer to Table 5.4 Measurable output rate and cutoff frequency combination for output rate setting.

0000: Reserved 0001: Reserved 0010: 1,000Sps 0011: 500Sps 0100: 200Sps 0101: 100Sps 0110: 50Sps

0111-1111: not used

*1) The factory setting is ODR: 200 Hz

Note) The maximum output rate is limited to 500 Sps when long-term filter is used.

7.12 FILTER_CTRL Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x07	-	-	-	-	-	-	-	-	-

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x06	-	-	FILTER_ STAT	-		FILTE	R_SEL		R/W *1

*1) Only FILTER_STAT is read-only.

bit[5] FILTER_STAT

This read-only status bit shows the status of the filter setting

1: Filter setting is busy

0: Filter setting is completed

bit[3:0] FILTER_SEL

Specifies the type of filter, TAP setting and cutoff frequency.

For the FIR Kaiser filter, these bits also selects the cutoff frequency. When using user defined FIR filter, please program the filter coefficient data

0000: Reserved

- 0001: FIR Kaiser Filter TAP=64, fc=83
- 0010: FIR Kaiser Filter TAP=64, fc=220
- 0011: FIR Kaiser Filter TAP=128, fc=36
- 0100: FIR Kaiser Filter TAP=128、fc=110
- 0101: FIR Kaiser Filter TAP=128、fc=350
- 0110: FIR Kaiser Filter TAP=512, fc=9
- 0111: FIR Kaiser Filter TAP=512, fc=16
- 1000: FIR Kaiser Filter TAP=512, fc=60
- 1001: FIR Kaiser Filter TAP=512, fc=210
- 1010: FIR Kaiser Filter TAP=512, fc=460
- 1011: User Defined FIR Filter TAP=4
- 1100: User Defined FIR Filter TAP=64
- 1101: User Defined FIR Filter TAP=128
- 1110: User Defined FIR Filter TAP=512

1111: not used

After writing to this bit, FILTER_STAT changes to 1 (during execution). Confirm the completion of the filter setting process by confirming that the FILTER_STAT bit returns to "0".

Note) For the combination of output rate and cutoff frequency considering avoidance of aliasing and transient response at sampling start, refer to 5.17.3 Notes on FIR filter.

Note) The factory settings are Tap: 512, Fc: 60 Hz

7.13 UART_CTRL Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x09				-			BAUD	_RATE	R/W

Addr (Hex)	Bit7		Bit2	Bit1	Bit0	R/W
0x08		-		AUTO _START	UART _AUTO	R/W

bit[9:8] BAUD_RATE

Note) The baud rate change using these **BAUD_RATE** bits become effective immediately after write access completes.

These bits specifies the Baud Rate of UART interface.

00: Reserved

01: 460.8kbps

10: 230.4kbps

11: 115.2kbps

bit[1] AUTO_START (Only valid for UART Auto sampling)

Enables or disables the Auto Start function.

1: Automatic Start is enabled

0: Automatic Start is disabled

When Auto Start is enabled, the device enters sampling mode and sends sampling data automatically after completing internal initialization after powered on.

Write a "1" to this **AUTO_START** bit and **UART_AUTO** bit of this register to enable this function. Then execute **FLASH_BACKUP** of GLOB_CMD [0x0A(W1)] bit [3] to preserve the current register settings.

bit[0] UART_AUTO

Note) This register bit must be set to 0 when using the SPI interface.

Enables or disables the UART Auto sampling function.

1: UART Auto sampling is selected

0: UART Manual sampling is selected

If UART Auto sampling is active, register values such as FLAG, temperature, and accelerations (XACCL, YACCL, ZACCL) are continuously transmitted automatically according to the data output rate set by SMPL_CTRL [0x04(W1)] register.

In UART Manual sampling, register data is transmitted as a response to a register read command.

Note) For more info on UART Auto sampling refer to 6.2.4 UART Auto Sampling Operation and 6.3 Data Packet Format. The burst output data is configured by register setting in BURST_CTRL [0x0C(W1)].

7.14 GLOB_CMD Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x0B	-	-	-	MESMOD _STAT	-	NOT _READY	-	-	R

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x0A	SOFT _RST	-	-	-	FLASH_ BACKUP	FLASH _RST	-	-	R/W

bit[12] MESMOD_STAT

This read-only status bit shows the status of the measurement condition at a sampling mode. 1: Reduced noise floor condition

0: Standard noise floor condition

bit[10] NOT_READY

Indicates whether this product currently ready. Immediately after power on, this bit is "1" and becomes "0" when the product is ready. After the power on, wait until the Power-On Start-Up Time has elapsed and then wait until this bit becomes "0" before starting sensor measurement. This bit is read-only.

1: Not ready

0: Ready

bit[7] SOFT_RST

Write "1" to execute software reset. After the software reset is completed, the bit automatically goes back to "0".

bit[3] FLASH_BACKUP

Write "1" to save the current values of the control registers with the O mark in the "Flash Backup" column of Table 7.1 to the non-volatile memory. After the execution is completed, the bit automatically goes back to "0". After confirming this bit goes back to "0" and then check the result in **FLASH_BU_ERR** of DIAG_STAT [0x04(W0)] bit [0].

bit[2] FLASH_RST

Write "1" to resets the setting value saved in the nonvolatile memory to the factory default state. After completion of execution, it will automatically return to "0". After confirming this bit goes back to "0" and then check the result in **FLASH_BU_ERR** of DIAG_STAT [0x04(W0)] bit [0]. The factory default state will be reflected to the registers after completing internal initialization after powered on or a reset.

7.15 BURST_CTRL Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x0D	FLAG _OUT	TEMP _OUT	-	-	-	ACCX _OUT	ACCY _OUT	ACCZ _OUT	R/W

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x0C	-	-	-	-	-	-	COUNT _OUT	CHKSM _OUT	R/W

These bits enable/disable the content in the output data for burst mode and UART Auto sampling.

bit[15] FLAG_OUT

Controls the output of FLAG status.

- 1: Enables output.
- 0: Disables output.

bit[10] ACCX OUT

Controls the output of X axis acceleration / tilt angle. The output mode is selected by **OUTPUT SEL X** of register: SIG CTRL [0x00 (W1)], bit [7].

- 1: Enables output.
- 0: Disables output.

bit[9] ACCY_OUT

Controls the output of Y axis acceleration / tilt angle. The output mode is selected by OUTPUT_SEL_Y of register: SIG CTRL [0x00 (W1)], bit [6].

- 1: Enables output.
- 0: Disables output.

bit[8] ACCZ OUT

Controls the output of Z axis acceleration / tilt angle. The output mode is selected by OUTPUT_SEL_Z of register: SIG CTRL [0x00 (W1)], bit [5].

- 1: Enables output.
- 0: Disables output.

COUNT OUT bit[1]

Controls the output of counter value.

- 1: Enables output.
- 0: Disables output.

bit[0] CHKSM OUT

Controls the output of checksum.

- 1: Enables output.
- 0: Disables output.

Note) Please set "1: Enables output" to at least one bit of bit[8:10]. All outputs of acceleration / tilt angle values cannot be desabled at the same time.

7.16 FIR UCMD Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x17		1	·	-	-	-	-	-	-

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x16	-	-	-	-	-	-	FIR_UCMD		R/W

FIR UCMD (FIR Filter User CoMmanD) bit[1:0]

These bits set the control command for setting the coefficient data of the user defined FIR filter. READ WRITE 00: execution complete do not execute

- 01: reading in progress read
- 10: writing in progress write not used
- 11: not used

7.17 FIR_UDATA Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x19	DATA _ERR	-	-	-	-	-	-	-	R
Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x18		FIR UDATA							

bit[15] DATA_ERR

This bit shows the state of the read error on the coefficient data of the user defined FIR filter.

1: Read error

0: Normal operation

bit[7:0] FIR_UDATA(FIR Filter User DATA)

Set the coefficient data (binary) of the user defined FIR filter.

7.18 FIR_UADDR Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	[/] R/W
0x1B				FIR_U _HI	ADDR GH				R/W
								N Y	
Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x1A					ADDR OW	EU			R/W

bit[15:8] FIR_UADDR_HIGH

Upper address of the coefficient data of the user FIR filter.

bit[7:0] FIR_UADDR_LOW

Lower address of the coefficient data of the user FIR filter.

Note) This address is automatically incremented after the read / write command is executed.

Note) The setting range is from 0x0800 to 0x0FFF. It cannot be set outside the range.

7.19 LONGFILT_CTRL Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x1D	-	-	-	-	-	-	-	-	-

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x1C	-	-	-	-	-	-	FILT_SEL	FILT_EN	R/W*1

bit[1] FILT_SEL

This bit selects the type of long period filter.

1: HPF

0: LPF

bit[0] FILT_EN

This bit enable / disable long-period filter.

1: Enable

0: Disable

7.20 LONGFILT_TAP Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x1F	-	·					- (<u> </u>	-
							h		
Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x1E	-	-	-	-		TAP_	SIZE		R/W

bit[3:0] TAP_SIZE

These bits set the tap size of the long period filter.

0001: tap2 0010: tap4 0011: tap8 0100: tap16 0101: tap32 0110: tap64 0111: tap128 1000: tap256 1001: tap512 1010: tap1024 1011: tap2048 1100: tap4096 1101~111: not used

7.21 XA_OFFSET Register (Window 1)

Addr (Hex)	Bit15		Bit8	R/W
0x2D		XOFFSET_HIGH_H		R/W

Addr (Hex)	Bit7		Bit0	R/W	
0x2C		XOFFSET_HIGH_L		R/W	

bit[15:0] XOFFSET_HIGH

Sets the X-axis acceleration offset value upper word.

Addr (Hex)	Bit15		Bit8	R/W
0x2F		XOFFSET_LOW_H		R/W

Addr (Hex)	Bit7		Bit0	R/W
0x2E		XOFFSET_LOW_L		R/W

bit[15:0] XOFFSET_LOW

Sets the X-axis acceleration offset value lower word.

7.22 YA_OFFSET Register (Window 1)

Addr (Hex)	Bit15			K	Bit8	R/W
0x31		YOFFSET_HIGH_H	н			R/W

Addr (Hex)	Bit7		Bit0	R/W
0x30		YOFFSET_HIGH_L		R/W

bit[15:0] YOFFSET_HIGH

Sets the Y-axis acceleration offset value upper word.

Addr (Hex)	Bit15		Bit8	R/W
0x33		YOFFSET_LOW_H		R/W

Addr (Hex)	Bit7		Bit0	R/W
0x32		YOFFSET_LOW_L		R/W

bit[15:0] YOFFSET_LOW

Sets the Y-axis acceleration offset value lower word.

7.23 ZA_OFFSET Register (Window 1)

Addr (Hex)	Bit15		Bit8	R/W		
0x35		ZOFFSET_HIGH_H				

Addr (Hex)	Bit7		Bit0	R/W
0x34		ZOFFSET_HIGH_L		R/W

bit[15:0] ZOFFSET_HIGH

Sets the Z-axis acceleration offset value upper word.

Addr (Hex)	Bit15		Bit8	R/W
0x37		ZOFFSET_LOW_H		R/W

Addr (Hex)	Bit7		Bit0	R/W
0x36		ZOFFSET_LOW_L		R/W

bit[15:0] ZOFFSET_LOW

Sets the Z-axis acceleration offset value upper word.

7.24 XA_ALARM Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x47		XALARM _UP							R/W

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x46					ARM LO				R/W

bit[15:8] XALARM_UP

Sets the acceleration upper limit value to be determined by XALARM_ERR of register:FLAG [0x06 (W0)], bit [4].

Data format :8bit, two's complement format

Setting Unit : G

Setting range :-15 to +15 (can not be set to a value outside the range)

bit[7:0] XALARM_LO

Sets the acceleration lower limit value to be determined by XALARM_ERR of register:FLAG [0x06 (W0)], bit [4]

The setting specification is the same as XALARM_UP

7.25 YA_ALARM Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x49		YALARM _UP					R/W		

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W	
0x48					ARM LO				R/W	

bit[15:8] YALARM_UP

Sets the acceleration upper limit value to be determined by YALARM_ERR of register:FLAG [0x06 (W0)], bit [3]

Data format : 8bit, two's complement format

Setting Unit : G

Setting range :-15 to +15 (can not be set to a value outside the range)

bit[7:0] YALARM_LO

Sets the acceleration lower limit value to be determined by YALARM_ERR of register:FLAG [0x06 (W0)], bit [3]

The setting specification is the same as YALARM_UP

7.26 ZA_ALARM Register (Window 1)

Addr (Hex)	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8	R/W
0x4B				ZAL/	ARM JP		K		R/W

Addr (Hex)	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	R/W
0x4A					ARM LO				R/W

bit[15:8] ZALARM_UP

Sets the acceleration upper limit value to be determined by ZALARM_ERR of register:FLAG [0x06 (W0)], bit [2]

Data format :8bit, two's complement format

Setting Unit : G

Setting range :-15 to +15 (can not be set to a value outside the range)

bit[7:0] ZALARM_LO

Sets the acceleration lower limit value to be determined by ZALARM_ERR of register:FLAG [0x06 (W0)], bit [2]

The setting specification is the same as ZALARM_UP

7.27 PROD_ID Register (Window 1)

Addr (Hex)	Bit15		Bit0	R/W		
0x6A		PROD_ID1				
0x6C	PROD_ID2					
0x6E	PROD_ID3					
0x70	PROD_ID4					

bit[15:0] Product ID

Note) These registers return the product model number represented in ASCII code.

Product ID return value is A352AD10

PROD_ID1:0x3341 PROD_ID2:0x3235 PROD_ID3:0x4441 PROD_ID4:0x3031

7.28 VERSION Register (Window 1)

Addr (Hex)	Bit15			Bit0	R/W
0x72		VERSION	$\boldsymbol{\lambda}$		R
6414E.0					

bit[15:0] Version

This register returns the Firmware Version

7.29 SERIAL_NUM Register (Window 1)

Addr (Hex)	Bit15	BitO	R/W	
0x74		SERIAL_NUM1	R	
0x76	SERIAL_NUM2			
0x78	SERIAL_NUM3			
0x7A		SERIAL_NUM4	R	

bit[15:0] Serial Number

Note) These registers return the serial number represented in ASCII code.

For example, if the Serial Number is 01234567 then the return value is:

SERIAL_NUM1:0x3130 SERIAL_NUM2:0x3332 SERIAL_NUM3:0x3534 SERIAL_NUM4:0x3736

7.30 WIN_CTRL Register (Window 0,1)

Addr (Hex)	Bit15		Bit8	R/W
0x7F		_		-

Addr (Hex)	Bit7		Bit0	R/W
0x7E		WINDOW_ID		R/W

bit[7:0] WINDOW_ID Selects the desired register window by writing the window number to this register.

0x00 :Window 0

0x01 :Window 1 0x02-0xFF: Unused

8. Sample Program Sequence

The following describes the recommended procedures for operating this device.

8.1 SPI Sequence

8.1.1 Power-on Sequence (SPI)

Power-on sequence is as follows. (a) Power-on. (b) Wait Power-On Start-Up Time. (c) Wait until NOT READY bit goes to 0. NOT READY is GLOB CMD[0x0A(W1)]'s bit[10]. TXdata={0xFE01}/ RXdata={0x----}. /* WINDOW ID(L) write command.(WINDOW=1) */ TXdata={0x0A00}/ RXdata={0x----}. /* GLOB CMD read command */ TXdata={0x----}/ ŔXdata={GLOB_CMD}. Confirm NOT_READY bit. /* get response */ When NOT READY becomes 0, it ends. Otherwise, please repeat (c). (d) Confirm HARD_ERR bits. HARD_ERR is DIAG_STAT[0x04(W0)]'s bit[7:5]. TXdata={0xFE00}/ RXdata={0x----}. /* WINDOW ID(L) write command.(WINDOW=0) */ TXdata={0x0400}/ RXdata={0x----}. /* DIAG STAT read command */ TXdata={0x----}/ RXdata={DIAG_STAT}. /* get response */ Confirm HARD_ERR is 000. If HARD_ERR is 000, the Accelerometer is OK. Otherwise, the Accelerometer is faulty. -: don't care

8.1.2 Register Read and Write (SPI)

[Read Example] To read a 16bit-data from a register(addr=0x02 / WINDOW=0). TXdata={0xFE00}/ RXdata={0x----}. /* WINDOW_I TXdata={0x0200}/ RXdata={0x----}. /* MODE_CTF TXdata={0x----}/ RXdata={0x0400}. /* get response

/* WINDOW_ID write command.(WINDOW=0) */ /* MODE_CTRL read command */ /* get response*/

0x04 in high byte of RXdata is Configuration mode. 0x00 in low byte of RXdata is Reserved.

Please note that read data unit is 16bit, and Most Significant Bit first in 16bit SPI.

[Write Example]

-: don't care

To write a 8bit-data into a register(addr=0x03 / WINDOW=0).

TXdata={0xFE00}/ RXdata={0x----}. /* WINDOW_ID(L) write command.(WINDOW=0) */

TXdata={0x8301}/ RXdata={0x----}. /* MODE_CTRL(H) write command.(move to Sampling mode) */ There is no response at Write.

-:don't care

By sending this command, the Accelerometer moves to Sampling mode.

Please note that write data unit is 8bit.

8.1.3 Sampling Data (SPI)

[Sample Flow 1 (SPI normal mode)]

Power-on sequence. Please refer to Chapter 8.1.1.

Filter setting sequence. Please refer to Chapter 8.1.9.

TXdata={0xFE01}/ RXdata={0x----}. /* WINDOW_ID(L) write command.(WINDOW=1) */ TXdata={0x8504}/ RXdata={0x----}. /* SMPL_CTRL(H) write command.(200Sps) */ TXdata={0x8800}/ RXdata={0x----}. /* UART_CTRL(L) write command.(disable UART Auto sampling) */

TXdata={0xFE00}/ RXdata={0x----}. /* WINDOW_ID(L) write command.(WINDOW=0) */ TXdata={0x8301}/ RXdata={0x----}. /* MODE_CTRL(H) write command.(move to Sampling mode) */ receive sampling data. (a)Wait until Data Ready signal is asserted. (b) TXdata={0x0E00}/ RXdata={----}. /* TEMP HIGH read command */ TXdata={0x1000}/ RXdata={TEMP HIGH}. /* TEMP LOW read command */ TXdata={0x3000}/ RXdata={ TEMP LOW }. /* XACCL HIGH read command */ TXdata={0x3200}/ RXdata={XACCL HIGH}. /* XACCL LOW read command */ TXdata={0x3400}/ RXdata={XACCL LOW}. /* YACCL HIGH read command */ TXdata={0x3600}/ RXdata={YACCL HIGH}. /* YACCL LOW read command */ TXdata={0x3800}/ RXdata={YACCL LOW}. /* ZACCL HIGH read command */ TXdata={0x3A00}/ RXdata={ZACCL_HIGH}. /* ZACCL LOW read command */ TXdata={0x0A00}/ RXdata={ZACCL LOW}. /* COUNT read command */ TXdata={0x----}/ RXdata={COUNT}. repeat from (a) to (b). TXdata={0x8302}/ RXdata={0x----}. /* MODE CTRL(H) write command.(return to Configulation mode) */ -: don't care Note) Please remember to wait until Data Ready signal is asserted. [Sample Flow 2 (SPI burst mode)] Power-on sequence. Please refer to Chapter 8.1.1. Filter setting sequence. Please refer to Chapter 8.1.9. TXdata={0xFE01}/ RXdata={0x----}. /* WINDOW_ID(L) write command.(WINDOW=1) */ /* SMPL CTRL(H) write command.(200Sps) */ TXdata={0x8504}/ RXdata={0x----}. /* UART_CTRL(L) write command.(disable UART_Auto sampling) */ TXdata={0x8800}/ RXdata={0x----}. TXdata={0x8C02}/ RXdata={0x----}. /* BURST CTRL(L) write command.(COUNT=on) */ TXdata= $\{0x8D47\}/RXdata=\{0x----\}$. /* BURST_CTRL(H) write command.(TEMP=on, ACC_XYZ=on) */ TXdata={0xFE00}/ RXdata={0x----}. /* WINDOW ID(L) write command.(WINDOW=0) */ TXdata={0x8301}/ RXdata={0x----}. /* MODE CTRL(H) write command.(move to Sampling mode) */ receive sampling data. (a)Wait until Data Ready signal is asserted. (b) TXdata={0x8000}/ RXdata={0x----}. /* BURST(L) write command */ TXdata={0x----}/ RXdata={TEMP HIGH}. TXdata={0x----}/ RXdata={TEMP_LOW}. TXdata={0x----}/ RXdata={XACCL_HIGH}. TXdata={0x----}/ RXdata={XACCL_LOW}. TXdata={0x----}/ RXdata={YACCL_HIGH}. TXdata={0x----}/ RXdata={YACCL_LOW}. TXdata={0x----}/ RXdata={ZACCL_HIGH}. TXdata={0x----}/ RXdata={ZACCL_LOW}. TXdata={0x----}/ RXdata={COUNT}. repeat from (a) to (b). TXdata={0x8302}/ RXdata={0x----}. /* MODE CTRL(H) write command.(return to Configulation mode) */ -: don't care Note) Please remember to wait until Data Ready signal is asserted.

8.1.4 Selftest (SPI)

Selftest is as follows.

Power-on sequence. Please refer to Chapter 8.1.1. (a) Send self test command. TXdata={0xFE01}/ RXdata={0x----}.

/* WINDOW_ID(L) write command.(WINDOW=1) */

8. Sample Program Sequence

TXdata={0x8304}/ RXdata={0x----}. /* MSC_CTRL(H) write command.(Acc Test) */ (b) Wait until selftest has finished. Wait until ACC_TEST bit goes to 0. ACC_TEST is MSC_CTRL[0x02(W1)]'s bit[10]. TXdata={0x0200}/ RXdata={0x----}. /* MSC_CTRL read command */ TXdata={0x----}/ RXdata={MSC CTRL}. /* get response */ Confirm ACC TEST bit. When ACC TEST becomes 0, it ends, Otherwise, please repeat (b), (c) Confirm the result. Confirm ACC ERR bits. ACC ERR is DIAG STAT[0x04(W0)]'s bit[15:12]. TXdata={0xFE00}/ RXdata={0x----}. /* WINDOW_ID(L) write command.(WINDOW=0) */ TXdata={0x0400}/ RXdata={0x----}. /* DIAG STAT read command */ TXdata={0x----}/ RXdata={DIAG STAT}. /* get response */ Confirm each ACC ERR is 0. If each ACC ERR is 0, the result is OK. Otherwise, the result is NG. -: don't care

8.1.5 Flash Test (SPI)

Flash test is as follows.

Power-on sequence. Please refer to Chapter 8.1.1. (a) Send flash test command. TXdata={0xFE01}/ RXdata={0x----}. /* WINDOW ID(L) write command.(WINDOW=1) */ TXdata={0x8308}/ RXdata={0x----}. /* MSC_CTRL(H) write command.(Flash Test) */ (b) Wait until flash test has finished. Wait until FLASH_TEST bit goes to 0. FLASH_TEST is MSC_CTRL[0x02(W1)]'s bit[11]. TXdata= $\{0x0200\}/RXdata=\{0x---\}$. /* MSC CTRL read command */ TXdata={0x----}/ RXdata={MSC_CTRL}. /* get response */ Confirm FLASH TEST bit. When FLASH TEST becomes 0, it ends. Otherwise , please repeat (b). (c) Confirm the result. Confirm FLASH ERR bits. FLASH ERR is DIAG STAT[0x04(W0)]'s bit[2]. TXdata={0xFE00}/ RXdata={0x----}. /* WINDOW_ID(L) write command.(WINDOW=0) */ TXdata={0x0400}/ RXdata={0x----}. /* DIAG STAT read command */ TXdata={0x----}/ RXdata={DIAG STAT}. /* get response */ Confirm FLASH ERR is 0. If FLASH ERR is 0, the result is OK. Otherwise, the result is NG.

8.1.6 Software Reset (SPI)

Software reset is as follows.

-:don't care

Power-on sequence. Please refer to Chapter 8.1.1. (a) Send software reset command. TXdata={0xFE01}/ RXdata={0x----}. /* WINDOW_ID(L) write command.(WINDOW=1) */ TXdata={0x8A80}/ RXdata={0x----}. /* GLOB_CMD(L) write command.(Software reset) */ (b) Wait Reset Recovery Time. -:don't care

8.1.7 Flash Backup (SPI)

Flash backup is as follows.

Power-on sequence. Please refer to Chapter 8.1.1. (a) Send flash backup command. TXdata={0xFE01}/ RXdata={0x----}. /* WINDOW ID(L) write command.(WINDOW=1) */ TXdata={0x8A08}/ RXdata={0x----}. /* GLOB_CMD(L) write command.(Flash backup) */ (b) Wait until flash backup has finished. Wait until FLASH BACKUP bit goes to 0. FLASH BACKUP is GLOB CMD[0x0A(W1)]'s bit[3]. TXdata= $\{0x0A00\}/RXdata=\{0x---\}$. /* GLOB CMD read command */ TXdata={0x----}/ RXdata={GLOB CMD}. /* get response */ Confirm FLASH BACKUP bit. When FLASH BACKUP becomes 0, it ends. Otherwise , please repeat (b). (c) Confirm the result. TXdata={0xFE00}/ RXdata={0x----}. /* WINDOW ID(L) write command.(WINDOW=0) */ Confirm FLASH_BU_ERR bits. FLASH_BU_ERR is DIAG_STAT[0x04(W0)]'s bit[0]. TXdata={0x0400}/ RXdata={0x----}. /* DIAG STAT read command */ TXdata={0x----}/ RXdata={DIAG STAT}. /* get response */ Confirm FLASH BU ERR is 0. If FLASH BU ERR is 0, the result is OK. Otherwise, the result is NG. -: don't care

8.1.8 Flash Reset (SPI)

Flash Reset is as follows.

Power-on sequence. Please refer to Chapter 8.1.1. (a) Send flash reset command. /* WINDOW ID(L) write command.(WINDOW=1) */ TXdata={0xFE01}/ RXdata={0x----}. TXdata= $\{0x8A04\}/RXdata=\{0x----\}$. /* GLOB_CMD(L) write command.(Flash Reset) */ (b) Wait until flash reset has finished. Wait until FLASH RST bit goes to 0. FLASH RST is GLOB CMD[0x0A(W1)]'s bit[2]. TXdata= $\{0x0A00\}/RXdata=\{0x---\}$. /* GLOB_CMD read command */ TXdata={0x----}/ RXdata={GLOB CMD}. /* get response */ Confirm FLASH RST bit. When FLASH_RST becomes 0, it ends. Otherwise , please repeat (b). (c) Confirm the result. TXdata={0xFE00}/ RXdata={0x----}. /* WINDOW_ID(L) write command.(WINDOW=0) */ Confirm FLASH BU ERR bits. FLASH BU ERR is DIAG STAT[0x04(W0)]'s bit[0]. TXdata={0x0400}/ RXdata={0x----}. /* DIAG STAT read command */ TXdata={0x----}/ RXdata={DIAG STAT}. /* get response */ Confirm FLASH_BU_ERR is 0. If FLASH BU ERR is 0, the result is OK. Otherwise, the result is NG. -: don't care (d) Power off and on, or reset. 8.1.9 Filter Setting (SPI) Filter setting is as follows. Power-on sequence. Please refer to Chapter 8.1.1. (a) Send filter setting command for FIR kaiser filter (TAP512, fc60). TXdata={0xFE01}/ RXdata={0x----}. /* WINDOW_ID(L) write command.(WINDOW=1) */ TXdata={0x8608}/ RXdata={0x----}. /* FILTER CTRL(L) write command.(Filter setting) */ (b) Wait until filter setting has finished. Wait until FILTER STAT bit goes to 0. FILTER STAT is FILTER CTRL[0x06(W1)]'s bit[5]. TXdata={0x0600}/ RXdata={0x----}. /* FILTER CTRL read command */

TXdata={0x----}/ RXdata={FILTER_CTRL}. /* get response */ Confirm FILTER_STAT bit. When FILTER_STAT becomes 0, it ends. Otherwise , please repeat (b).

8.1.10 User Defined FIR Filter Coefficients Setting (SPI)

User Defined FIR Filter coefficients setting is as follows.

Power-on sequence. Please refer to Chapter 8.1.1.

[Write Sequence] (a) Send filter coefficient address command. TXdata={0xFE01}/ RXdata={0x}. First, set the start address (0x0800), TXdata={0x9B08}/ RXdata={0x}. TXdata={0x9A00}/ RXdata={0x}.	/* WINDOW_ID(L) write command.(WINDOW=1) */ /* FIR_UADDR(H) write command.(Address High Byte) */ /* FIR_UADDR(L) write command.(Address Low Byte) */					
(b) Send filter coefficient data command. For example, if the coefficient data is 0x1C19E TXdata={0x9853}/ RXdata={0x}.	0153, send in order from the lower byte(0x53). /* FIR_UDATA(L) write command */					
(c) Send filter coefficient control command. TXdata={0x9602}/ RXdata={0x}.	/* FIR_UCMD(L) write command (Wirte execution)*/					
(d) Wait until Write execution has finished. Wait until FIR_UCMD bit goes to 00. FIR_UCM TXdata={0x1600}/ RXdata={0x}. TXdata={0x}/ RXdata={FIR_UCMD}. Confirm FIR_UCMD bit. When FIR_UCMD becomes 00, it ends. Other	/* FIR_UCMD read command */ /* get response */					
(e) Repeat from (b) to (d) until sending all coefficients.						
(f) Send filter setting command for User Defined FIR Filter. Please refer to Chapter 8.1.9.						
[Read Sequence] (a) Send filter coefficient address command.						
TXdata={0xFE01}/ RXdata={0x}. First, set the start address (0x0800), TXdata={0x9B08}/ RXdata={0x}. TXdata={0x9A00}/ RXdata={0x}.	/* WINDOW_ID(L) write command.(WINDOW=1) */ /* FIR_UADDR(H) write command.(Address High Byte) */ /* FIR_UADDR(L) write command.(Address Low Byte) */					
TXdata={0xFE01}/ RXdata={0x}. First, set the start address (0x0800), TXdata={0x9B08}/ RXdata={0x}.	/* FIR_UADDR(H) write command.(Address High Byte) */					
TXdata={0xFE01}/ RXdata={0x}. First, set the start address (0x0800), TXdata={0x9B08}/ RXdata={0x}. TXdata={0x9A00}/ RXdata={0x}. (b) Send filter coefficient control command.	<pre>/* FIR_UADDR(H) write command.(Address High Byte) */ /* FIR_UADDR(L) write command.(Address Low Byte) */ /* FIR_UCMD(L) write command (Read execution)*/ ID is FIR_UCMD[0x16(W1)]'s bit[1:0]. /* FIR_UCMD read command */ /* get response */</pre>					

TXdata={0x----}/ RXdata={FIR_UDATA}. /* get response */

(e) Repeat from (b) to (d) until reading all coefficients.

notes

The coefficient data unit is 32bit, and little-endian format.

After the byte has completed reading, the address is automatically incremented by 1.

8.1.11 Sleep Sequence (SPI)

Sleep sequence is as follows.

Power-on sequence. Please refer to Chapter 8.1.1. (a) Enter Sleep mode TXdata={0xFE00}/ RXdata={0x----}. /* WINDOW_ID(L) write command.(WINDOW=0) */ TXdata={0x8303}/ RXdata={0x----}. /* MODE_CTRL(H) write command.(move to sleep mode) */

(b) Wake up from Sleep mode

Wake up from sleep mode and move to config mode by detecting an edge trigger on the EXT pin. After waiting Sleep Wake-up Time, can access the registers in SPI interface.

notes

SPI communication is not possible during sleep mode.

8.1.12 Reduced Noise Floor Condition Setting (SPI)

Reduced noise floor condition setting is as follows.

Power-on sequence. Please refer to Chapter 8.1.1.

(a) Send a Reduced noise floor condition selection command.

`TXdata={0xFE01}/ RXdata={0x----}. /* WINDOW_ID(L) write command.(WINDOW=1) */ TXdata={0x8014}/ RXdata={0x----}. /* SIG_CTRL(L) write command.(select measurement condition) */

(b) Execute Flash backup. Please refer to Chapter 8.1.7.

(c) Power off and on.

(d) Wait Powe<mark>r-On Start-Up Time</mark>.

(e) Confirm measurement condition selection state.

 TXdata={0xFE01}/ RXdata={0x----}.
 /* WINDOW_ID(L) write command.(WINDOW=1) */

 Confirm MESMOD_STAT bits. MESMOD_STAT is GLOB_CMD[0x0A(W1)]'s bit[12].

 TXdata={0x0A00}/ RXdata={0x----}.
 /* GLOB_CMD read command */

 TXdata={0x----}/ RXdata={GLOB_CMD}.
 /* get response */

 Confirm MESMOD_STAT bit.
 When MESMOD_STAT is 1, it is possible to select the Reduced noise floor condition.

(f) Select the Reduced noise floor condition

TXdata={0xFE00}/ RXdata={0x}.	/* WINDOW_ID(L) write command.(WINDOW=0) */
TXdata={0x8301}/ RXdata={0x}.	/* MODE_CTRL(H) write command.(move to sampling mode) */

8.1.13 Bias Offset Setting (SPI)

Bias offset setting is as follows.

Power-on sequence. Please refer to Chapter 8.1.1. (a) Send bias offset setting command. For example, if X axis bias offset value is +1.23G (0x013AE147),

```
TXdata={0xFE01}/ RXdata={0x----}.
TXdata={0xAD01}/ RXdata={0x----}.
TXdata={0xAC3A}/ RXdata={0x----}.
TXdata={0xAFE1}/ RXdata={0x----}.
TXdata={0xAE47}/ RXdata={0x----}.
```

/* WINDOW_ID(L) write command.(WINDOW=1) */ /* XA_OFFSET_HIGH(H) write command. */ /* XA_OFFSET_HIGH(L) write command. */ /* XA_OFFSET_LOW(H) write command. */

/* XA_OFFSET_LOW(L) write command. */

8.1.14 Alarm Threshold Setting (SPI)

Alarm threshold settig is as follows.

Power-on sequence. Please refer to Chapter 8.1.1.

(a) Send alarm threshold setting command.

For example, if X axis alarm threshold value is +5G/-5G,

TXdata={0xFE01}/ RXdata={0x----}.

TXdata={0xC705}/ RXdata={0x----}.

TXdata={0xC6FB}/ RXdata={0x----}.

/* WINDOW_ID(L) write command.(WINDOW=1) */

/* XA_ALARM write command. (upper limit value)*/

/* XA_ALARM write command. (lower limit value)*/

8.2 UART Sequence

8.2.1 Power-on Sequence (UART)

Power-on sequence is as follows.

(a) power-on.

(b) Wait Power-On Start-Up Time. (c) Wait until NOT READY bit goes to 0. NOT READY is GLOB CMD[0x0A(W1)]'s bit[10]. $TXdata=\{0xFE,0x01,0x0d\}.$ /* WINDOW_ID(L) write command.(WINDOW=1) */ $TXdata=\{0x0A,0x00,0x0d\}.$ /* GLOB CMD read command */ TXdata={0x0A,MSByte,LSByte,0x0d}. /* get response */ Confirm NOT READY bit. When NOT READY becomes 0, it ends. Otherwise, please repeat (c). (d) Confirm HARD ERR bits. HARD ERR is DIAG STAT[0x04(W0)]'s bit[7:5]. $TXdata=\{0xFE,0x00,0x0d\}.$ /* WINDOW ID(L) write command.(WINDOW=0) */ TXdata= $\{0x04, 0x00, 0x0d\}$. /* DIAG STAT read command */ TXdata={0x04,MSByte,LSByte,0x0d}. /* get response */ Confirm HARD ERR is 000. If HARD ERR is 000, the Accelerometer is OK. Otherwise, the Accelerometer is faulty.

8.2.2 Register Read and Write (UART)

[Read Example] To read a 16bit-data from a register(addr=0x02 / WINDOW=0). TXdata={0xFE,0x00,0x0d}. TXdata={0x02,0x00,0x0d}. RXdata={0x02,0x04,0x00,0x0d}. /* get response*/

0x04 in 2nd byte of RXdata is Configuration mode. 0x00 in 3rd byte of RXdata is Reserved. Please note that read data unit is 16bit, and Most Significant Byte first.

[Write Example]

To write a 8bit-data into a register(addr=0x03 / WINDOW=0). TXdata={0xFE,0x00,0x0d}. /* WINDOW_ID(L) write command.(WINDOW=0) */ TXdata={0x83,0x01,0x0d}. /* MODE_CTRL(H) write command.(move to Sampling mode) */ There is no response at Write.

By sending this command, the Accelerometer moves to Sampling mode. Please note that write data unit is 8bit.

8.2.3 Sampling Data (UART)

[Sample Flow 1 (UART Auto sampling)] Power-on sequence. Please refer to Chapter 8.2.1. Filter setting sequence. Please refer to Chapter 8.2.9. TXdata= $\{0xFE, 0x01, 0x0d\}$. /* WINDOW_ID(L) write command.(WINDOW=1) */ $TXdata = \{0x85, 0x04, 0x0d\}.$ /* SMPL CTRL(H) write command.(200Sps) */ /* UART CTRL(L) write command.(UART Auto sampling) */ TXdata={0x88,0x01,0x0d}. TXdata= $\{0x8C, 0x02, 0x0d\}$. /* BURST CTRL(L) write command.(COUNT=on) */ $TXdata=\{0x8D,0x47,0x0d\}.$ /* BURST CTRL(H) write command.(TEMP=on, ACC XYZ=on) */ $TXdata=\{0xFE,0x00,0x0d\}.$ /* WINDOW ID(L) write command.(WINDOW=0) */ TXdata={0x83,0x01,0x0d}. /* MODE CTRL(H) write command.(move to Sampling mode) */ receive sampling data. (a)RXdata={0x80, TEMP_HIGH_Hi, TEMP_HIGH_Lo, TEMP_LOW_Hi, TEMP_LOW_Lo, XACCL HIGH HI, XACCL HIGH Lo, XACCL LOW HI, XACCL LOW Lo, YACCL_HIGH_Hi, YACCL_HIGH_Lo, YACCL_LOW_Hi, YACCL_LOW_Lo,

ZACCL_HIGH_Hi, ZACCL_HIGH_Lo, ZACCL_LOW_Hi, ZACCL_LOW_Lo, COUNT_Hi, COUNT_Lo, 0x0d} repeat (a). TXdata={0x83,0x02,0x0d}. /* MODE_CTRL(H) write command.(return to Configulation mode) */

[Sample Flow 2(UART burst mode)] Power-on sequence. Please refer to Chapter 8.2.1. Filter setting sequence. Please refer to Chapter 8.2.9. TXdata={0xFE,0x01,0x0d}. /* WINDOW ID(L) write command.(WINDOW=1) */ TXdata={0x85,0x04,0x0d}. /* SMPL CTRL(H) write command.(200Sps) */ $TXdata = \{0x88, 0x00, 0x0d\}.$ /* UART_CTRL(L) write command.(UART Manual sampling) */ /* BURST CTRL(L) write command.(COUNT=on) */ TXdata={0x8C,0x02,0x0d}. TXdata= $\{0x8D,0x47,0x0d\}$. /* BURST CTRL(H) write command.(TEMP=on, ACC XYZ=on) */ TXdata={0xFE,0x00,0x0d}. /* WINDOW ID(L) write command.(WINDOW=0) */ TXdata={0x83,0x01,0x0d}. /* MODE CTRL(H) write command.(move to Sampling mode) */ receive sampling data. (a)Wait until Data Ready signal is asserted. (b)TXdata={0x80,0x00,0x0d}. /* BURST(L) write command */ (c)RXdata={0x80, TEMP_HIGH_Hi, TEMP_HIGH_Lo, TEMP_LOW_Hi, TEMP_LOW_Lo, XACCL_HIGH_Hi, XACCL_HIGH_Lo, XACCL_LOW_Hi, XACCL_LOW_Lo, YACCL_HIGH_Hi, YACCL_HIGH_Lo, YACCL_LOW_Hi, YACCL_LOW_Lo, ZACCL_HIGH_Hi, ZACCL_HIGH_Lo, ZACCL_LOW_Hi, ZACCL_LOW_Lo, COUNT Hi, COUNT Lo, 0x0d} repeat from (a) to (c). TXdata={0x83,0x02,0x0d}. /* MODE CTRL(H) write command.(return to Configulation mode) */

Note) Please remember to wait until Data Ready signal is asserted.

[Notes]

Please note that read data unit is 16bit, and Most Significant Byte first. Please note that write data unit is 8bit.

X ACCL HIGH Hi: means MSByte of ACCL HIGH data

X ACCL_HIGH_Lo: means LSByte of ACCL_HIGH data

8.2.4 Selftest (UART)

Selftest is as follows.

Power-on sequence. Please refer to Chapter 8.2.1. (a) Send self test command. $TXdata=\{0xFE,0x01,0x0d\}.$ /* WINDOW ID(L) write command.(WINDOW=1) */ TXdata={0x83,0x04,0x0d}. /* MSC CTRL(H) write command.(Acc Test) */ (b) Wait until selftest has finished. Wait until ACC TEST bit goes to 0. ACC TEST is MSC CTRL[0x02(W1)]'s bit[10]. TXdata={0x02,0x00,0x0d}. /* MSC_CTRL read command */ RXdata={0x02,MSByte,LSByte,0x0d}. /* get response */ Confirm ACC_TEST bit. When ACC_TEST becomes 0, it ends. Otherwise , please repeat (b). (c) Confirm the result. Confirm ACC_ERR bits. ACC_ERR is DIAG_STAT[0x04(W0)]'s bit[15:12]. TXdata={0xFE,0x00,0x0d}. /* WINDOW_ID(L) write command.(WINDOW=0) */ TXdata={0x04,0x00,0x0d}. /* DIAG STAT read command */ RXdata={0x04,MSByte,LSByte,0x0d}. /* get response */ Confirm each ACC_ERR is 0. If each ACC_ERR is 0, the result is OK. Otherwise, the result is NG.

8.2.5 Flash Test (UART)

Flash test is as follows.

Power-on sequence. Please refer to Ch (a) Send flash test command. TXdata={0xFE,0x01,0x0d}. TXdata={0x83,0x08,0x0d}.	apter 8.2.1. /* WINDOW_ID(L) write command.(WINDOW=1) */ /* MSC_CTRL(H) write command.(Flash Test) */	
TXdata={0x02,0x00,0x0d}. RXdata={0x02,MSByte,LSByte,0x0d}. Confirm FLASH_TEST bit. When FLASH_TEST becomes 0, it end	/* get response */	
 (c) Confirm the result. Confirm FLASH_ERR bits. FLASH_ERR is DIAG_STAT[0x04(W0)]'s bit[2]. TXdata={0xFE,0x00,0x0d}. /* WINDOW_ID(L) write command.(WINDOW=0) */ TXdata={0x04,0x00,0x0d}. /* DIAG_STAT read command */ RXdata={0x04,MSByte,LSByte,0x0d}. /* get response */ Confirm FLASH_ERR is 0. If FLASH_ERR is 0, the result is OK. Otherwise, the result is NG. 		
8.2.6 Software Reset (UART)		

Software reset is as follows.

Power-on sequence. Please refer to Chapter 8.2.1. (a) Send software reset command. TXdata={0xFE,0x01,0x0d}. TXdata={0x8A,0x80,0x0d}. (b) Wait Reset Recovery Time. (c) Send software reset of the sector of the

8.2.7 Flash Backup (UART)

Flash backup is as follows.

Power-on sequence. Please refer to Ch	apter 8.2.1.
(a) Send flash backup command.	
TXdata={0xFE,0x0 <mark>1,0x</mark> 0d}.	/* WINDOW_ID(L) write command.(WINDOW=1) */
TXdata={0x8A,0x08,0x0d}.	/* GLOB_CMD(L) write command.(Flash backup) */
(b) Wait until flash backup has finished.	
Wait until FLASH_BACKUP bit goes to	0. FLASH_BACKUP is GLOB_CMD[0x0A(W1)]'s bit[3].
TXdata={0x0A,0x00,0x0d}.	/* GLOB_CMD read command */
RXdata={0x0A,MSByte,LSByte,0x0d}.	/* get response */
Confirm FLASH_BACKUP bit.	
When FLASH_BACKUP becomes 0, it	ends. Otherwise , please repeat (b).
(c) Confirm the result.	
	_BU_ERR is DIAG_STAT[0x04(W0)]'s bit[0].
TXdata={0xFE,0x00,0x0d}.	/* WINDOW_ID(L) write command.(WINDOW=0) */
TXdata={0x04,0x00,0x0d}.	/* DIAG_STAT read command */
RXdata={0x04,MSByte,LSByte,0x0d}.	/* get response */
Confirm FLASH_BU_ERR is 0.	
If FLASH_BU_ERR is 0, the result is C	DK. Otherwise, the result is NG.

8.2.8 Flash Reset (UART)

Flash Reset is as follows.

TXdata={0x8A,0x04,0x0d}. /* GL0 (b) Wait until flash reset has finished. Wait until FLASH_RST bit goes to 0. FLASH_	NDOW_ID(L) write command.(WINDOW=1) */ OB_CMD(L) write command.(Flash Reset) */ RST is GLOB_CMD[0x0A(W1)]'s bit[2].
TXdata={0x0A,0x00,0x0d}. /* GL0 RXdata={0x0A,MSByte,LSByte,0x0d}. /* get Confirm FLASH_RST bit. When FLASH_RST becomes 0, it ends. Othe	
(c) Confirm the result. Confirm FLASH_BU_ERR bits. FLASH_BU_E TXdata={0xFE,0x00,0x0d}. /* WIN TXdata={0x04,0x00,0x0d}. /* DIA RXdata={0x04,MSByte,LSByte,0x0d}. /* get Confirm FLASH_BU_ERR is 0. If FLASH_BU_ERR is 0, the result is OK. Oth	NDOW_ID(L) write command.(WINDOW=0) */ G_STAT read command */ response */
(d) Power off and on , or reset.	
8.2.9 Filter Setting (UART)	
Filter setting is as follows.	
Power-on sequence. Please refer to Chapter 8 (a) Send filter setting command for FIR kaiser 1 TXdata={0xFE,0x01,0x0d}. TXdata={0x86,0x08,0x0d}. (b) Wait until filter setting has finished. Wait until FILTER_STAT bit goes to 0. FILTEF TXdata={0x06,0x00,0x0d}. /* FILT RXdata={0x06,MSByte,LSByte,0x0d}. /* get Confirm FILTER_STAT bit. When FILTER_STAT becomes 0, it ends. Oth	filter (TAP512, fc60). /* WINDOW_ID(L) write command.(WINDOW=1) */ /* FILTER_CTRL(L) write command.(Filter setting) */ R_STAT is FILTER_CTRL[0x06(W1)]'s bit[5]. TER_CTRL read command */ response */
8.2.10 User Defined FIR Filter Coefficien	ts Setting (UART)
User Defined FIR Filter coefficients setting is a	s follows.
Power-on sequence. Please refer to Chapter 8	.2.1.
[Write Sequence] (a) Send filter coefficient address command. TXdata={0xFE,0x01,0x0d}. First, set the start address (0x0800), TXdata={0x9B,0x08,0x0d}.	/* WINDOW_ID(L) write command.(WINDOW=1) */ /* FIR_UADDR(H) write command.(Address High Byte) */
TXdata={0x9A,0x00,0x0d}. (b) Send filter coefficient data command. For example, if the coefficient data is 0x1C19 TXdata={0x98,0x53,0x0d}.	/* FIR_UADDR(L) write command.(Address Low Byte) */ D153, send in order from the lower byte(0x53). /* FIR_UDATA(L) write command */

(c) Send filter coefficient control command. TXdata={0x96,0x02,0x0d}. /* FIR_UCMD(L) write command (Wirte execution)*/		
(d) Wait until Write execution has finished. Wait until FIR_UCMD bit goes to 00. FIR_UCMD is FIR_UCMD[0x16(W1)]'s bit[1:0]. TXdata={0x16,0x00,0x0d}. /* FIR_UCMD read command */ RXdata={0x16,MSByte,LSByte,0x0d}. /* get response */ Confirm FIR_UCMD bit. When FIR_UCMD becomes 00, it ends. Otherwise , please repeat (d).		
(e) Repeat from (b) to (d) until sending all coefficients.		
(f) Send filter setting command for User Defined FIR Filter. Please refer to Chapter 8.2.9.		
notes The coefficient data unit is 32bit, and little-endian format. After the byte has completed writing, the address is automatically incremented by 1.		
[Read Sequence] (a) Send filter coefficient address command. TXdata={0xFE,0x01,0x0d}. First, set the start address (0x0800), TXdata={0x9B,0x08,0x0d}. TXdata={0x9A,0x00,0x0d}. /* WINDOW_ID(L) write command.(WINDOW=1) */ /* FIR_UADDR(H) write command.(Address High Byte) */ /* FIR_UADDR(L) write command.(Address Low Byte) */		
(b) Send filter coefficient control command. TXdata={0x96,0x01,0x0d}. /* FIR_UCMD(L) write command (Read execution)*/		
(c) Wait until Read execution has finished. Wait until FIR_UCMD bit goes to 00. FIR_UCMD is FIR_UCMD[0x16(W1)]'s bit[1:0]. TXdata={0x16,0x00,0x0d}. /* FIR_UCMD read command */ RXdata={0x16,MSByte,LSByte,0x0d}. /* get response */ Confirm FIR_UCMD bit. When FIR_UCMD becomes 00, it ends. Otherwise , please repeat (c).		
(d) Send filter coefficient data command. TXdata={0x18,0x00,0x0d}. /* FIR_UDATA read command */ RXdata={0x18,MSByte,LSByte,0x0d}. /* get response */		
(e) Repeat from (b) to (d) until reading all coefficients.		
notes The coefficient data unit is 32bit, and little-endian format. After the byte has completed reading, the address is automatically incremented by 1.		
8.2.11 Sleep Sequence (UART)		
Sleep sequence is as follows.		
Power-on sequence. Please refer to Chapter 8.2.1. (a) Enter Sleep mode TXdata={0xFE,0x00,0x0d}. /* WINDOW_ID(L) write command.(WINDOW=0) */ TXdata={0x83,0x03,0x0d}. /* MODE_CTRL(H) write command.(move to sleep mode) */		
(b) Wake up from Sleep mode Wake up from sleep mode and move to config mode by detecting an edge trigger on the EXT pin. After waiting Sleep Wake-up Time, can access the registers in UART interface.		

notes

UART communication is not possible during sleep mode.

8.2.12 Reduced Noise Floor Condition Setting (UART)

Reduced noise floor condition setting is as follows.

Power-on sequence. Please refer to Chapter 8.2.1. (a) Send a Reduced noise floor condition selection command. $TXdata=\{0xFE,0x01,0x0d\}.$ /* WINDOW ID(L) write command.(WINDOW=1) */ $TXdata = \{0x80, 0x14, 0x0d\}.$ /* SIG CTRL(L) write command.(select measurement condition) */ (b) Execute Flash backup. Please refer to Chapter 8.2.7. (c) Power off and on. (d) Wait Power-On Start-Up Time. (e) Confirm measurement condition selection state. $TXdata=\{0xFE,0x01,0x0d\}$. /* WINDOW ID(L) write command.(WINDOW=1) */ Confirm MESMOD STAT bits. MESMOD STAT is GLOB CMD[0x0A(W1)]'s bit[12]. TXdata= $\{0x0A, 0x00, 0x0d\}$. /* GLOB CMD read command */ RXdata={0x0A,MSByte,LSByte,0x0d}. /* get response */ Confirm MESMOD STAT bit. When MESMOD STAT is 1, it is possible to select the Reduced noise floor condition. (f) Select the Reduced noise floor condition TXdata={0xFE,0x00,0x0d}. /* WINDOW ID(L) write command.(WINDOW=0) */ $TXdata = \{0x83, 0x01, 0x0d\}.$ /* MODE_CTRL(H) write command.(move to Sampling mode) */

8.2.13 Bias Offset Setting (UART)

Bias offset setting is as follows.

 Power-on sequence. Please refer to Chapter 8.2.1.

 (a) Send bias offset setting command.

 For example, if X axis bias offset value is +1.23G (0x013AE147),

 TXdata={0xFE,0x01,0x0d}.
 /* WINDOW_ID(L) write command.(WINDOW=1) */

 TXdata={0xAD,0x01,0x0d}.
 /* XA_OFFSET_HIGH(H) write command. */

 TXdata={0xAC,0x3A,0x0d}.
 /* XA_OFFSET_HIGH(L) write command. */

 TXdata={0xAF,0xE1,0x0d}.
 /* XA_OFFSET_LOW(H) write command. */

 TXdata={0xAE,0x47,0x0d}.
 /* XA_OFFSET_LOW(L) write command. */

8.2.14 Alarm Threshold Setting (UART)

Alarm threshold settig is as follows.

Power-on sequence. Please refer to Chapter 8.2.1. (a) Send alarm threshold setting command. For example, if X axis alarm threshold value is +5G/-5G, TXdata={0xFE,0x01,0x0d}. TXdata={0xC7,0x05,0x0d}. TXdata={0xC6,0xFB,0x0d}. /* XA_ALARM write command. (upper limit value)*/

8.2.15 Auto Start (UART only)

Auto Start is as follows.

Power-on sequence. Please refer to Chapter 8.2.1. (a) Set registers. /* WINDOW_ID(L) write command.(WINDOW=1) */ TXdata={0xFE,0x01,0x0d}. TXdata={0x85,0x04,0x0d}. /* SMPL CTRL(H) write command. (200Sps) */ /* FILTER CTRL(L) write command.(Filter setting TAP=512 fc60) */ TXdata={0x86,0x08,0x0d}. TXdata= $\{0x88,0x03,0x0d\}$. /* UART CTRL(L) write command.(UART Auto sampling, Auto start=on) */ TXdata={0x8C,0x02,0x0d}. /* BURST CTRL(L) write command.(COUNT=on) */ /* BURST_CTRL(H) write command.(TEMP=on, ACC_XYZ=on) */ TXdata={0x8D,0x47,0x0d}. (b) Execute Flash backup. Please refer to Chapter 8.2.7. (c) power-off. (d) power-on. (e) Wait Power-On Start-Up Time. (f) receive sampling data. (i) Wait until Data Ready signal is asserted. (ii) RXdata={0x80, TEMP_HIGH_Hi, TEMP_HIGH_Lo, TEMP_LOW_Hi, TEMP_LOW_Lo, XACCL_HIGH_Hi, XACCL_HIGH_Lo, XACCL_LOW_Hi, XACCL_LOW_Lo, YACCL_HIGH_Hi, YACCL_HIGH_Lo, YACCL_LOW_Hi, YACCL_LOW_Lo, ZACCL HIGH Hi, ZACCL HIGH Lo, ZACCL LOW Hi, ZACCL LOW Lo, COUNT_Hi, COUNT_Lo, 0x0d} repeat from (i) to (ii). (q) If you want to stop sampling, TXdata={0x83,0x02,0x0d}. /* MODE_CTRL(H) write command.(return to Configulation mode) */

9. Handling Notes

9.1 Cautions for Use

- When you attach the product to a housing, equipment, jig, or tool, make sure you attach it properly so that no mechanical stress is added to create a distortion such as a warp or twist. In addition, tighten the screws firmly but not too firmly because the mount of the product may break. Use screw locking techniques as necessary.
- When you set up the product, make sure the equipment, jigs, tools, and workers maintain a good ground in order not to generate high voltage leakage. If you add overcurrent or static electricity to the product, the product may be damaged permanently.
- When you install the product, make sure metallic or other conductors do not enter the product. Otherwise, malfunction or damage of the product may result.
- If excessive shock is added to the product when, for example, the product falls, the quality of the product may be degraded. Make sure the product does not fall when you handle it.
- Before you start using the product, test it in the actual equipment under the actual operating environment.
- Since the product has capacitors inside, inrush current will occur during power-on. Evaluate in the actual environment in order to check the effect of the supply voltage drop by inrush current in the system.
- If water enters the product, malfunction or damage of the product may result. If the product can be exposed to water, the system must have a waterproof structure. We do not guarantee the operation of the product when the product is exposed to condensation, dust, oil, corrosive gas (salt, acid, alkaline, or the like), or direct sunlight.
- This product is not designed to be radiation resistant.
- Never use this product if the operating condition is over the absolute maximum rating. If you do, the characteristics of the product may never recover.
- If the product is exposed to excessive exogenous noise or the like, degradation of the precision, malfunction, or damage of the product may result. The system needs to be designed so that the noise itself is suppressed or the system is immune to the noise.
- Mechanical vibration or shock, continuous mechanical stress, rapid temperature change, or the like may cause cracks or disconnections at the various connecting parts.
- Take sufficient safety measure for the equipment this product is built into.
- This product is not intended for general use by the consumer but instead for engineering design. For the customer, please consider it safely with the proper use.
- This product is not designed to be used in the equipment that demands extremely high reliability and where its failure may threaten human life or property (for example, aerospace equipment, submarine repeater, nuclear power control equipment, life support equipment, medical equipment, transportation control equipment, etc.). Therefore, Seiko Epson Corporation will not be liable for any damages caused by the use of the product for those applications.
- Do not alter or disassemble the product.

9.2 Cautions for Storage

- Do not add shock or vibration to the packing box. Do not spill water over the packing box. Do not store or use the product in the environment where dew condensation occurs due to rapid temperature change.
- To suppress the characteristic change by prolonged storage, it is recommended to maintain the environment at normal temperature and normal humidity. Normal temperature: +5 ~ +35 °C Normal humidity: 45%RH ~ 85%DH (JIS Z 8703).
- Do not store the product in a location subject to High Temperature, high humidity, under direct sunlight, corrosive gas or dust.
- Do not put mechanical stress on the product while it is stored.

9.3 Other Cautions

- When you connect the socket to the header of this product, make sure you do not insert the header in the reverse orientation. If you do, the product may be damaged permanently.
- The gloss marks derived from the adhesive material may have appeared on the casing surface of the product, but it does not affect the function and quality of the product.
- The Parting line as a result of die cast manufacturing process may have appeared on the casing surface of the product, but it is not an abnormality.
- Please take care not to tamper with or accidently disturb the assembly screw on the surface where the serial number is printed when attaching and detaching the product to the system. We do not guarantee the performance and the quality of the product in case the assembly screw is manipulated.
- The product contains quartz crystal oscillator created by microfabrication. Take precaution to prevent falling or excessive impact. Do not use the product after an accidental fall or it experiences excessive impact. The possibility of a failure and risk of malfunction from failure increases.
- If a radio (transmission antenna) is set up near this product, degradation of the precision may result by radio frequency interference. Place the radio (transmission antenna) as far away as possible or add shielding to mitigate the effects of radio frequency interference.
- Never turn off power while the host communicates the product. Otherwise, malfunction of the product may result.
- Small performance deterioration due to long-term use and aging effects, etc. cannot be detected through the self-diagnosis test in this product. Discontinue use immediately even when the self-diagnosis test results in a "pass" when experiencing abnormality in the sensor performance.
- If noise is induced on the external trigger terminal, there is a possibility an invalid measurement process is unintentionally sent to the host. To prevent this, when using an external trigger, take precaution to minimize noise on the external trigger terminal.
- Exercise care and precaution with the packaging and during transport of the equipment that this product is installed on to avoid excessive vibration and or damage from impact.

9.4 Limited Warranty

• The product warranty period is one year from the date of shipment. If a defect due to a quality failure of the product is found during the warranty period, we will promptly provide a replacement.

10. Part Number / Ordering Info.

The product can be ordered with the following numbers. Please inquire separately about details.

Table 10.1 Product Model Number

Product Model Number	Product Name	Comments
X2F000011000100	M-A352AD10	-

11. Evaluation Tools

Evaluation tools can be provided for the M-A352. For details, contact our representatives.

Table 11.1 Evaluation Tool Model Number

Product Model Number	Product Name	Comments
X2H000021000200	M-G32EV041	USB Evaluation Board for M-A352AD10
		*Works with Logger Software.
X2H000021000300	M-G32EV051	Relay board for M-A352AD10
		*Combination with M-G32EV041 is possible.

Revision History

Rev. No.	Date	Page	Category	Contents
Rev 20191009	2019/10/09	All	New	Newly established
Rev 20191213	2019/12/13	P8	Update	Table 3.2 Recommended socket parts at the host side
Rev 20220401	2022/4/1	P76	Modify	Product Number Change



EPSON

AMERICA

EPSON AMERICA, INC. Headquarter: 3131 Katella Ave. Los Alamitos, CA 90720, USA Phone: +1-800-463-7766

San Jose Office: 2860 Zanker Road, Suite 204, San Jose, CA 95134, U.S.A Phone: +1-800-463-7766

EUROPE

EPSON EUROPE ELECTRONICS GmbH Riesstrasse 15, 80992 Munich,

GERMANY Phone: +49-89-14005-0 FAX: +49-89-14005-110

International Sales Operations

ASIA

EPSON (CHINA) CO., LTD. 4F,Tower 1 of China Central Place,81 Jianguo Street, Chaoyang District, Beijing 100025 CHINA Phone: +86-400-810-9972 X ext.2 Mail EPSON_MSM@ecc.epson.com.cm

EPSON SINGAPORE PTE. LTD.

438B Alexandra Road, Block B Alexandra TechnoPark, #04-01/04, Singapore 119968 Phone: +65-6586-5500 FAX: +65-6271-3182

EPSON TAIWAN TECHNOLOGY & TRADING LTD. 15F, No.100, Song Ren Road,Taipei 110, TAIWAN Phone: +886-2-8786-6688 Fax: +886-2-8786-6660

EPSON KOREA Co., Ltd.

10F Posco Tower Yeoksam, Teheranro 134 Gangnam-gu, Seoul, 06235 KOREA Phone: +82-2-558-4270 Fax: +82-2-3420-6699

JAPAN

SEIKO EPSON CORPORATION. MD SALES & MARKETING DEPT.

JR Shinjuku Miraina Tower, 4-1-6 Shinjuku, Shinjuku-ku, Tokyo, 160-8801, Japan Phone: +81-3-6682-4322 FAX: +81-3-6682-5016

Revised date APR. 2022 in JAPAN

Disclaimer

ALL PRODUCTS, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Texim Europe B.V. its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Texim"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Texim makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product.

It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application.

Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time.

All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts.

Please contact us if you have any questions about the contents of the datasheet.

This may not be the latest version of the datasheet. Please check with us if a later version is available.





Headquarters & Warehouse

Elektrostraat 17 NL-7483 PG Haaksbergen The Netherlands

T:	+31 (0)53 573 33 33
E:	info@texim-europe.com
Homepage:	www.texim-europe.com





The Netherlands

Elektrostraat 17 NL-7483 PG Haaksbergen

T: +31 (0)53 573 33 33 E: nl@texim-europe.com



Belgium

Zuiderlaan 14, box 10 B-1731 Zellik

T: +32 (0)2 462 01 00 E: belgium@texim-europe.com



UK & Ireland

St Mary's House, Church Lane Carlton Le Moorland Lincoln LN5 9HS

T: +44 (0)1522 789 555 E: uk@texim-europe.com



Germany - North

Bahnhofstrasse 92 D-25451 Quickborn

T: +49 (0)4106 627 07-0 E: germany@texim-europe.com



Germany - South

Martin-Kollar-Strasse 9 D-81829 München

T: +49 (0)89 436 086-0 E: muenchen@texim-europe.com



Austria

Warwitzstrasse 9 A-5020 Salzburg

T: +43 (0)662 216 026 E: austria@texim-europe.com



Nordic

Søndre Jagtvej 12 DK-2970 Hørsholm

T: +45 88 20 26 30 E: nordic@texim-europe.com



Italy

Via Matteotti 43 IT-20864 Agrate Brianza (MB)

T: +39 (0)39 9713293 E: italy@texim-europe.com

www.texim-europe.com